

DC Brushless Motor Drivers for Cooling Fans

Speed Controllable Single-phase Full-wave DC Brushless Fan Motor Drivers BD6709FS, BD6718FV, BD6721FS, BD6722FS



●Description

This is the summary of models that suit for 12V speed controllable fan for desktop PC and general consumer equipment. They employ Bi-CDMOS process, and realize low ON resistance, low power consumption. They incorporate lock protection and automatic restart circuit, current limiting circuit.

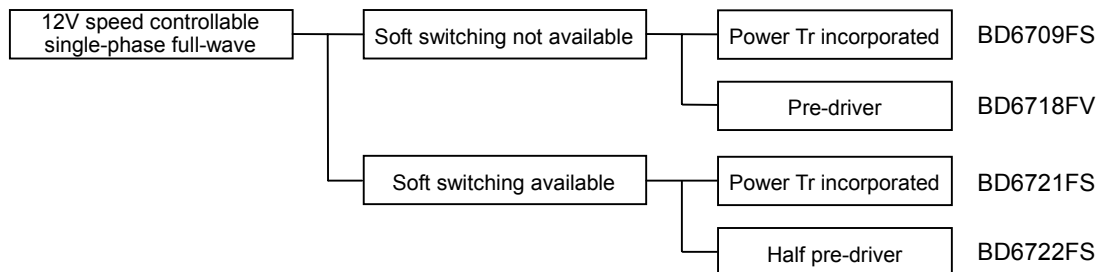
●Features

- 1) Power Tr incorporated (BD6709FS, BD6721FS)
- 2) Pre-driver compatible for external Tr (BD6718FV)
- 3) Low side power Tr incorporated half pre-driver (BD6722FS)
- 4) Current limiting circuit
- 5) PWM soft switching driver (BD6721FS, BD6722FS)
- 6) Soft start circuit (BD6722FS)
- 7) Lock protection and automatic restart circuit
- 8) Rotating speed pulse signal (FG) output
- 9) Lock alarm signal (AL) output (BD6718FV, BD6721FS, BD6722FS)

● Application

For 12V fan for desktop PC, server and general consumer equipment

●Lineup



●Absolute Maximum Ratings

◎BD6709FS

| Parameter | Symbol | Limit | Unit |
|--------------------------|--------|----------|------|
| Supply voltage | Vcc | 17 | V |
| Power dissipation | Pd | 812.5 * | mW |
| Operation temperature | Topr | -40~+95 | °C |
| Storage temperature | Tstg | -55~+150 | °C |
| Output current | Iomax | 1.2 * * | A |
| FG signal output current | IFG | 10 | mA |
| FG signal output voltage | VFG | 15 | V |
| Junction temperature | Tjmax | 150 | °C |

* Reduce by 6.5mW/°C over 25°C.
(On 70.0mm×70.0mm×1.6mm glass epoxy board)

* * This value is not to exceed Pd.

◎BD6718FV

| Parameter | Symbol | Limit | Unit |
|--------------------------|--------|----------|------|
| Supply voltage | Vcc | 15 | V |
| Power dissipation | Pd | 812.5 * | mW |
| Operation temperature | Topr | -40~+95 | °C |
| Storage temperature | Tstg | -55~+150 | °C |
| High side output voltage | VOH | 36 | V |
| Low side output voltage | VOL | 15 | V |
| Low side output current | Iomax | 20 | mA |
| FG signal output current | IFG | 8 | mA |
| FG signal output voltage | VFG | 15 | V |
| AL signal output current | IAL | 8 | mA |
| AL signal output voltage | VAL | 15 | V |
| VREF current ability | IVREF | 4 | mA |
| HB current ability | IHB | 8 | mA |
| Junction temperature | Tjmax | 150 | °C |

* Reduce by 6.5mW/°C over 25°C.
(On 70.0mm×70.0mm×1.6mm glass epoxy board)

◎BD6721FS

| Parameter | Symbol | Limit | Unit |
|--------------------------|--------|----------|------|
| Supply voltage | Vcc | 20 | V |
| Power dissipation | Pd | 812.5 * | mW |
| Operation temperature | Topr | -40~+100 | °C |
| Storage temperature | Tstg | -55~+150 | °C |
| Output current | Iomax | 1.0 * * | A |
| FG signal output current | IFG | 10 | mA |
| FG signal output voltage | VFG | 20 | V |
| AL signal output current | IAL | 10 | mA |
| AL signal output voltage | VAL | 20 | V |
| VREF current ability | IVREF | 8 | mA |
| Junction temperature | Tjmax | 150 | °C |

* Reduce by 6.5mW/°C over 25°C.
(On 70.0mm×70.0mm×1.6mm glass epoxy board)

* * This value is not to exceed Pd.

◎BD6722FS

| Parameter | Symbol | Limit | Unit |
|--------------------------|---------|----------|------|
| Supply voltage | Vcc | 20 | V |
| Power dissipation | Pd | 812.5 * | mW |
| Operation temperature | Topr | -40~+100 | °C |
| Storage temperature | Tstg | -55~+150 | °C |
| High side output voltage | VOH | 34 | V |
| Low side output voltage | VOL | 34 | V |
| Low side output current | Iomax | 1.5 * * | A |
| Signal output current | IFG/IAL | 10 | mA |
| Signal output voltage | VFG/VAL | 20 | V |
| VREF current ability | IVREF | 8 | mA |
| VTH input voltage | VVTH | 15 | V |
| Junction temperature | Tjmax | 150 | °C |

* Reduce by 6.5mW/°C over 25°C.
(On 70.0mm×70.0mm×1.6mm glass epoxy board)

* * This value is not to exceed Pd.

●OPERATING CONDITIONS

◎BD6709FS

| Parameter | Symbol | Limit | Unit |
|--------------------------------|--------|-------------|------|
| Operating supply voltage range | Vcc | 6.0~14.0 | V |
| Hall input voltage range | VH | 0.5~Vcc-1.5 | V |

◎BD6718FV

| Parameter | Symbol | Limit | Unit |
|--------------------------------|--------|-----------|------|
| Operating supply voltage range | Vcc | 4.5~14.0 | V |
| Hall input voltage range | VH | 0~Vcc-2.0 | V |

◎BD6721FS

| Parameter | Symbol | Limit | Unit |
|--------------------------------|--------|-----------|------|
| Operating supply voltage range | Vcc | 5.0~17.0 | V |
| Hall input voltage range | VH | 0~Vcc-2.0 | V |
| VTH input voltage range | VVTH | 0~Vcc-2.0 | V |
| VMIN input voltage range | VVMIN | 0~Vcc-2.0 | V |

◎BD6722FS

| Parameter | Symbol | Limit | Unit |
|--------------------------------|--------|-----------|------|
| Operating supply voltage range | Vcc | 5.0~17.0 | V |
| Hall input voltage range | VH | 0~Vcc-2.0 | V |
| VMIN input voltage range | VVMIN | 0~Vcc-2.0 | V |

● ELECTRICAL CHARACTERISTICS (Unless otherwise specified Ta=25°C, Vcc=12V)

◎BD6709FS

| Parameter | Symbol | Limit | | | Unit | Conditions | Characteristics |
|-------------------------------|-------------------|-------|------|------|------|--|-----------------|
| | | Min. | Typ. | Max. | | | |
| Circuit current | I _{cc} | 3.0 | 6.0 | 9.0 | mA | | Fig.1 |
| Hall input hysteresis | V _{HYS} | ±5 | ±10 | ±15 | mV | | Fig.2 |
| Output low voltage | V _{OL} | - | 0.2 | 0.3 | V | I _o =200mA | Fig.3,4 |
| Output high voltage | V _{OH} | - | 0.2 | 0.3 | V | I _o =-200mA Voltage between output and V _{cc} | Fig.5,6 |
| Lock detection ON time | T _{ON} | 0.30 | 0.50 | 0.70 | sec | | Fig.7 |
| Lock detection OFF time | T _{OFF} | 2.5 | 4.0 | 5.5 | sec | | Fig.8 |
| FG output low voltage | V _{FGL} | - | - | 0.3 | V | I _{FG} =5mA | Fig.9,10 |
| FG output leak current | I _{FGL} | - | - | 50 | μA | V _{FG} =15V | - |
| OSC low voltage | V _{OSCL} | 1.5 | 2.0 | 2.5 | V | | Fig.11 |
| OSC high voltage | V _{OSCH} | 3.0 | 3.5 | 4.0 | V | | Fig.12 |
| OSC frequency | F _{OSC} | - | 25 * | - | kHz | C _{OSC} =470pF | - |
| Level amp gain | GLA | 50 | - | - | dB | | - |
| Level amp output low voltage | V _{LAOL} | - | 0.9 | 1.2 | V | I _{LAOUT} =1mA | - |
| Level amp output high voltage | V _{LAOH} | - | 1.2 | 1.5 | V | I _{LAOUT} =-1mA Voltage between output and V _{cc} | - |
| VREF voltage | V _{REF} | 4.0 | 4.4 | 4.8 | V | I _{VREF} =-1mA | Fig.14,15 |
| CL-CS offset voltage | V _{cofs} | - | - | 30 | mV | | |

* This voltage is reference, not guarantee.

◎BD6718FV

| Parameter | Symbol | Limit | | | Unit | Conditions | Characteristics |
|----------------------------|-------------------|-------|------|------|------|---|-----------------|
| | | Min. | Typ. | Max. | | | |
| Circuit current | I _{cc} | 4.0 | 8.0 | 12.0 | mA | | Fig.16 |
| Hall input hysteresis | V _{HYS} | ±5 | ±10 | ±15 | mV | | Fig.17 |
| H side output current | I _H | 5 | 10 | 20 | mA | | Fig.18 |
| H side output leak current | I _{HL} | - | - | 100 | μA | | - |
| L side output high voltage | V _{LH} | - | 0.2 | 0.35 | V | I _o =-10mA Voltage between output and V _{cc} | Fig.19 |
| L side output low voltage | V _{LL} | - | 0.2 | 0.35 | V | I _o =10mA | Fig.20 |
| Lock detection ON time1 | T _{ON1} | 0.15 | 0.3 | 0.5 | sec | SEL(6PIN) : OPEN or H | Fig.21 |
| Lock detection OFF time1 | T _{OFF1} | 1.5 | 3.0 | 5.0 | sec | SEL(6PIN) : OPEN or H | Fig.22 |
| Lock detection ON time2 | T _{ON2} | 0.15 | 0.3 | 0.5 | sec | SEL(6PIN)=L | Fig.21 |
| Lock detection OFF time2 | T _{OFF2} | 3.0 | 6.0 | 10 | sec | SEL(6PIN)=L | Fig.23 |
| FG output low voltage | V _{FGL} | - | 0.3 | 0.4 | V | I _{FG} =5mA | Fig.24 |
| AL output low voltage | V _{VALL} | - | 0.3 | 0.4 | V | I _{AL} =5mA | Fig.24 |
| FG output leak current | I _{FGL} | - | - | 50 | μA | V _{FG} =15V | - |
| AL output leak current | I _{VALL} | - | - | 50 | μA | V _{AL} =15V | - |
| OSC low voltage | V _{OSCL} | 0.4 | 0.7 | 1.0 | V | | Fig.25 |
| OSC high voltage | V _{OSCH} | 1.2 | 1.5 | 1.8 | V | | Fig.26 |
| OSC frequency | F _{OSC} | - | 25 * | - | kHz | C _{OSC} =470pF | - |
| VREF voltage | V _{REF} | 2.2 | 2.5 | 2.8 | V | I _{VREF} =-1mA | Fig.27 |
| Hall bias voltage | V _{HB} | 1.2 | 1.5 | 1.8 | V | | Fig.28 |
| CR current ability | I _{CR} | 3 | - | - | mA | V _{CR} =1.5V | - |
| CR output low voltage | V _{CR} | - | 0.3 | 0.5 | V | I _{CR} =0.5mA | Fig.29 |
| CR discharge time | T _{CR} | 9 | 18.5 | 28 | μsec | | Fig.30 |

* This voltage is reference, not guarantee.

| Parameter | Symbol | Limit | | | Unit | Conditions | Characteristics |
|-------------------------------------|-------------------|-------|------|------|------|--|-----------------|
| | | Min. | Typ. | Max. | | | |
| Circuit current | I _{CC} | 4.0 | 7.0 | 10.0 | mA | | Fig.31 |
| Hall input hysteresis | V _{HYS} | ±5 | ±10 | ±15 | mV | | Fig.32 |
| Output voltage | V _O | - | 0.6 | 0.9 | V | I _o =300mA Upper and Lower total | Fig.33~36 |
| Lock detection ON time | T _{ON} | 0.30 | 0.50 | 0.70 | sec | | Fig.37 |
| Lock detection OFF time | T _{OFF} | 3.0 | 5.0 | 7.0 | sec | | Fig.38 |
| FG output low voltage | V _{FGL} | - | 0.15 | 0.3 | V | I _{FG} =5mA | Fig.39,40 |
| FG output leak current | I _{FGL} | - | - | 50 | μA | V _{FG} =17V | Fig.41 |
| AL output low voltage | V _{ALL} | - | 0.15 | 0.3 | V | I _{AL} =5mA | Fig.39,40 |
| AL output leak current | I _{ALL} | - | - | 50 | μA | V _{AL} =17V | Fig.41 |
| OSC low voltage | V _{OSCL} | 0.8 | 1.0 | 1.2 | V | | Fig.42 |
| OSC high voltage | V _{OSCH} | 2.3 | 2.5 | 2.7 | V | | Fig.43 |
| OSC charge current | I _{COSC} | -50 | -32 | -26 | μA | | Fig.44 |
| OSC discharge current | I _{DOSC} | 26 | 32 | 50 | μA | | Fig.44 |
| Level amp gain | G _{LA} | 50 | - | - | dB | | - |
| Level amp output low voltage | V _{LAOL} | - | 0.2 | 0.3 | V | | - |
| Level amp output high voltage | V _{LAOH} | - | 1.6 | 2.0 | V | Voltage between LAOUT and V _{CC} | - |
| Output ON Duty 1 | D _{UTY1} | 85 | 90 | 95 | % | V _{TH} =V _{REF} *0.383 OUT1=Pull up 1kΩ COSC=470pF | - |
| Output ON Duty 2 | D _{UTY2} | 45 | 50 | 55 | % | V _{TH} =V _{REF} *0.583 OUT1=Pull up 1kΩ COSC=470pF | - |
| Output ON Duty 3 | D _{UTY3} | 5 | 10 | 15 | % | V _{TH} =V _{REF} *0.783 OUT1=Pull up 1kΩ COSC=470pF | - |
| V _{REF} voltage | V _{REF} | 2.8 | 3.0 | 3.2 | V | I _{VREF} =-2mA | Fig.45 |
| Current limit voltage | V _{CL} | 290 | 310 | 330 | mV | | Fig.46 |
| V _{TH} input bias current | I _{VTH} | - | - | 0.2 | μA | | Fig.47 |
| V _{MIN} input bias current | I _{VMIN} | - | - | 0.2 | μA | | Fig.48 |

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| Parameter | Symbol | Limit | | | Unit | Conditions | Characteristics |
|-------------------------------------|-------------------|-------|------|------|------|---|-----------------|
| | | Min. | Typ. | Max. | | | |
| Circuit current | I _{CC} | 5.0 | 8.0 | 11.0 | mA | | Fig.52 |
| Hall input hysteresis | V _{HYS} | ±5 | ±10 | ±15 | mV | | Fig.53 |
| High side output current | I _H | 5 | 10 | 20 | mA | | Fig.54 |
| High side output leak current | I _{HL} | - | - | 10 | μA | V _H =34V | Fig.55 |
| Low side output voltage | V _L | - | 0.3 | 0.45 | V | I _o =600mA | Fig.56,57 |
| Lock detection ON time | T _{ON} | 0.18 | 0.3 | 0.42 | sec | | Fig.58 |
| Lock detection OFF time | T _{OFF} | 3.6 | 6.0 | 8.4 | sec | | Fig.59 |
| FG output low voltage | V _{FGL} | - | 0.15 | 0.3 | V | I _{FG} =5mA | Fig.61,62 |
| FG output leak current | I _{FGL} | - | - | 10 | μA | V _{FG} =17V | Fig.60 |
| AL output low voltage | V _{ALL} | - | 0.15 | 0.3 | V | I _{AL} =5mA | Fig. 61,62 |
| AL output leak current | I _{ALL} | - | - | 10 | μA | V _{AL} =17V | Fig.60 |
| OSC low voltage | V _{OSCL} | 0.8 | 1.0 | 1.2 | V | | Fig.63 |
| OSC high voltage | V _{OSCH} | 2.24 | 2.44 | 2.64 | V | | Fig.64 |
| OSC charge current | I _{COSC} | -50 | -32 | -26 | μA | | Fig.65 |
| OSC discharge current | I _{DOSC} | 26 | 32 | 50 | μA | | Fig.65 |
| Output ON Duty 1 | DUTY1 | 75 | 80 | 85 | % | V _{TH} =V _{REF} *0.429 A1H=Pull up 1kΩ COSC=470pF | - |
| Output ON Duty 2 | DUTY2 | 45 | 50 | 55 | % | V _{TH} =V _{REF} *0.573 A1H=Pull up 1kΩ COSC=470pF | - |
| Output ON Duty 3 | DUTY3 | 15 | 20 | 25 | % | V _{TH} =V _{REF} *0.717 A1H=Pull up 1kΩ COSC=470pF | - |
| V _{REF} voltage | V _{REF} | 2.8 | 3.0 | 3.2 | V | I _{VREF} =-2mA | Fig.66,67 |
| Current limit voltage | V _{CL} | 320 | 350 | 380 | mV | | Fig.68 |
| V _{TH} input bias current | I _{VTH} | - | - | 0.2 | μA | | Fig.69 |
| V _{MIN} input bias current | I _{VMIN} | - | - | 0.2 | μA | | Fig.70 |

● Truth table

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| H+ | H- | OUT1 | OUT2 | FG |
|----|----|------|------|----|
| H | L | L | H | H |
| L | H | H | L | L |

©BD6718FV

| H+ | H- | CR | A1H | A1L | A2H | A2L | FG |
|----|----|----|------|-----|------|-----|----|
| H | L | H | Hi-Z | H | L | L | H |
| L | H | H | L | L | Hi-Z | H | L |

©BD6721FS

| H+ | H- | OUT1 | OUT2 | FG |
|----|----|------|------|----|
| H | L | L | H | H |
| L | H | H | L | L |

©BD6718FV

| H+ | H- | A1H | A1L | A2H | A2L | FG |
|----|----|------|------|------|------|----|
| H | L | Hi-Z | L | L | Hi-Z | H |
| L | H | L | Hi-Z | Hi-Z | L | L |

◎BD6709FS

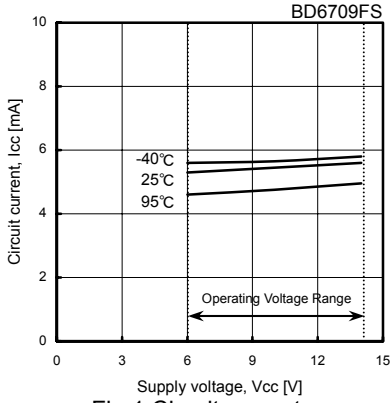


Fig.1 Circuit current

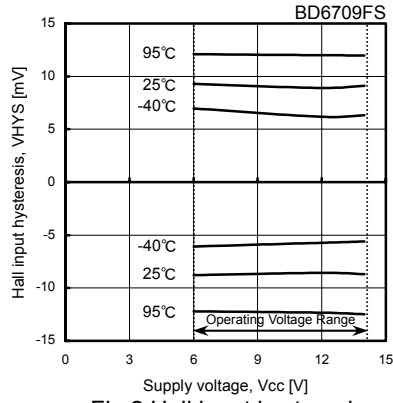


Fig.2 Hall input hysteresis

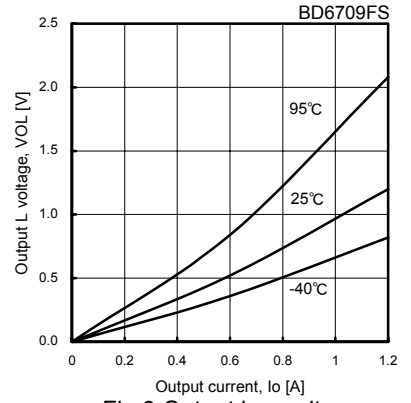


Fig.3 Output low voltage (Temperature characteristics)

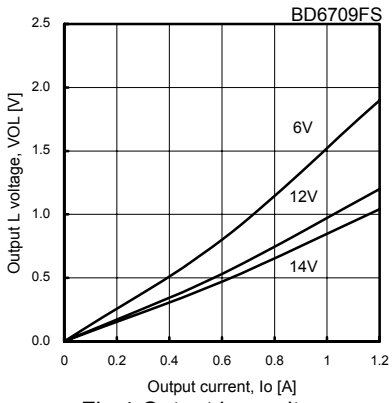


Fig.4 Output low voltage (Voltage characteristics)

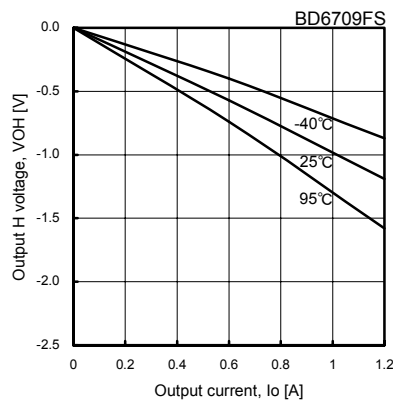


Fig.5 Output high voltage (Temperature characteristics)

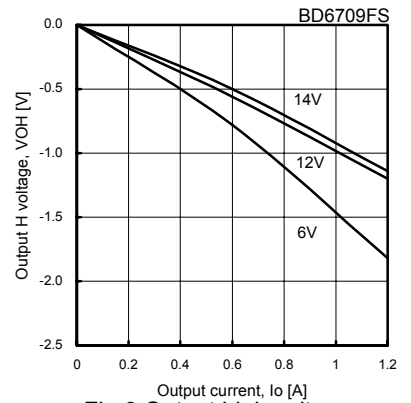


Fig.6 Output high voltage (Voltage characteristics)

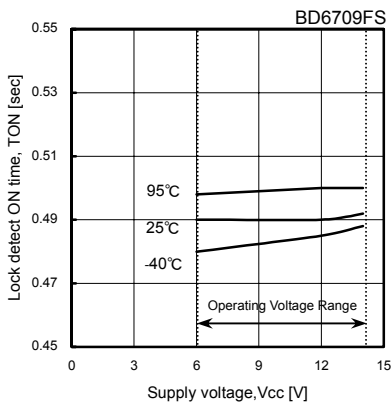


Fig.7 Lock detection ON time

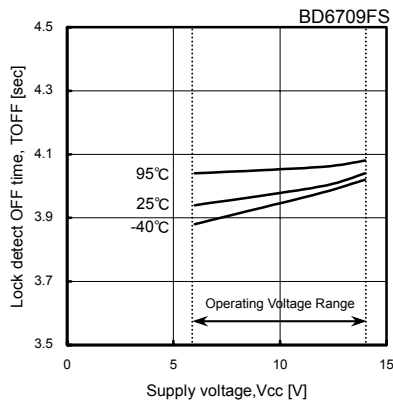


Fig.8 Lock detection OFF time

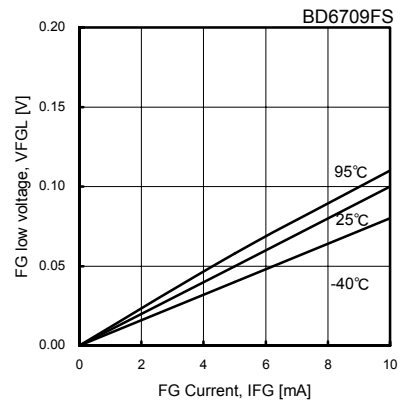


Fig.9 FG low voltage (Temperature characteristics)

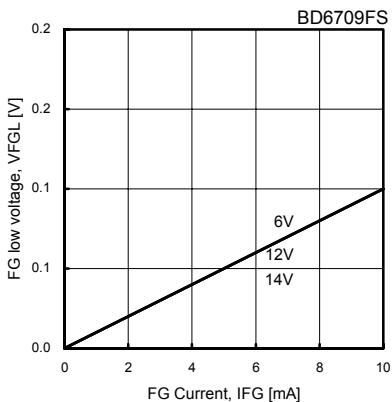


Fig.10 FG low voltage (Voltage characteristics)

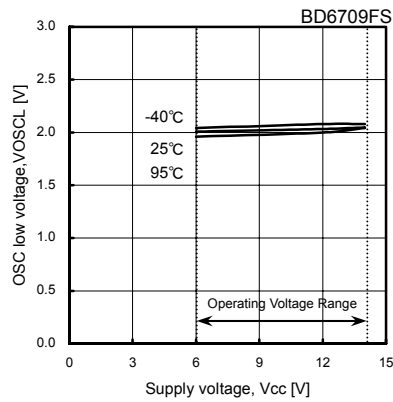


Fig.11 OSC low voltage

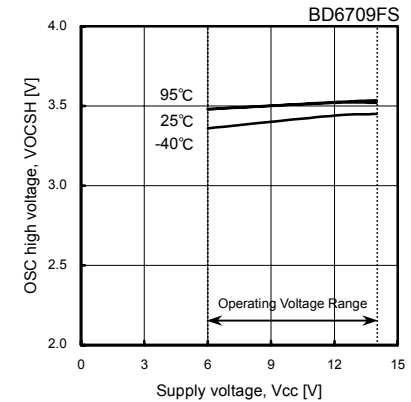


Fig.12 OSC high voltage

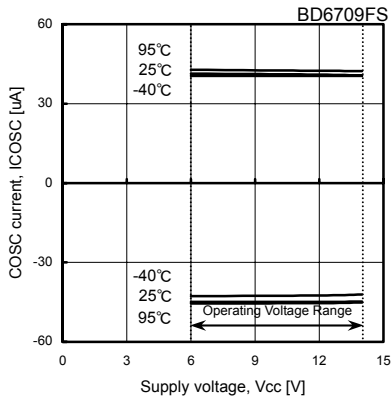


Fig.13 COSC charge discharge current

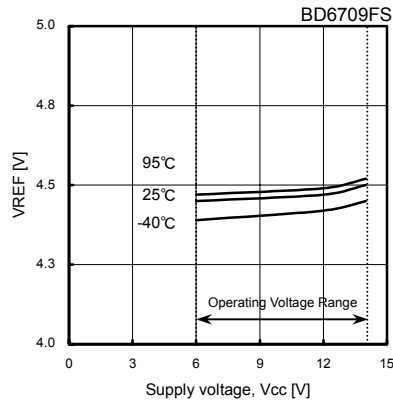


Fig.14 VREF voltage

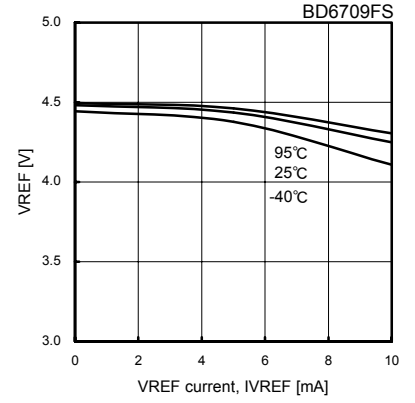


Fig.15 VREF current ability

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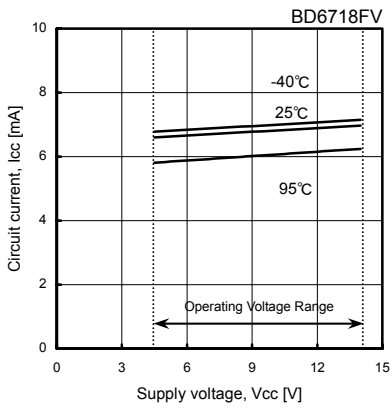


Fig.16 Circuit current

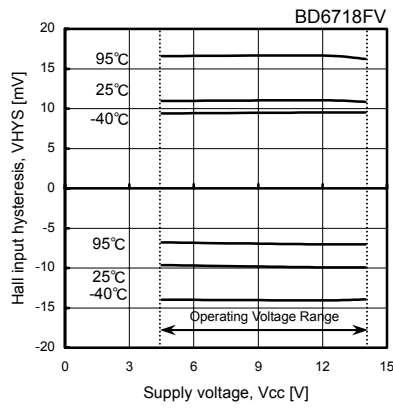


Fig.17 Hall input hysteresis

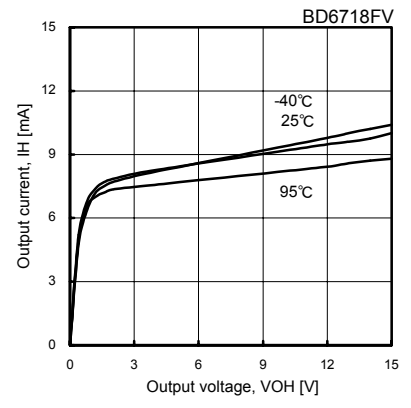


Fig.18 H side output current

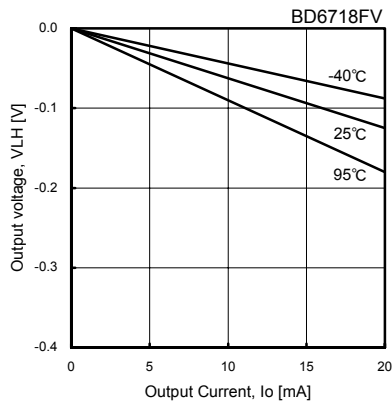


Fig.19 L side output high voltage

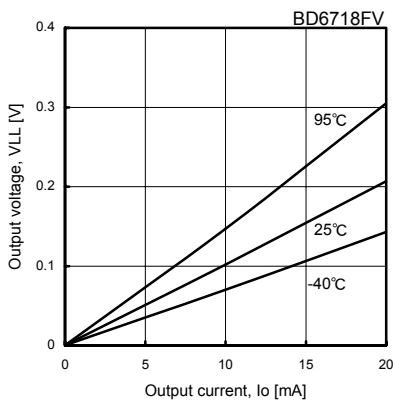


Fig.20 L side output low voltage

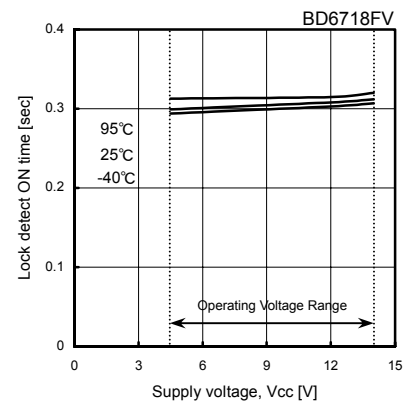


Fig.21 Lock detection ON time1,2

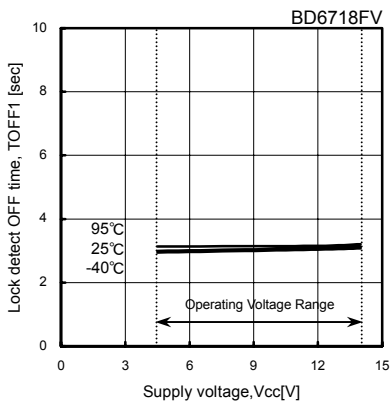


Fig.22 Lock detection OFF time1

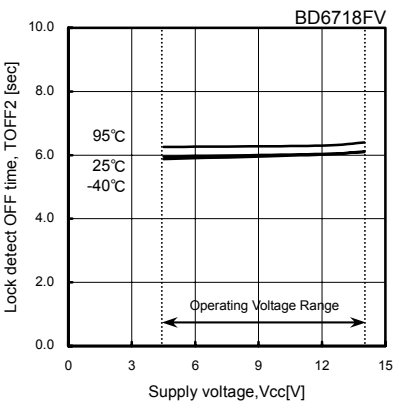


Fig.23 Lock detection OFF time2

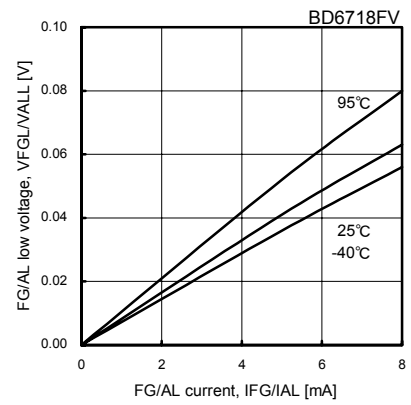


Fig.24 FG/AL low voltage

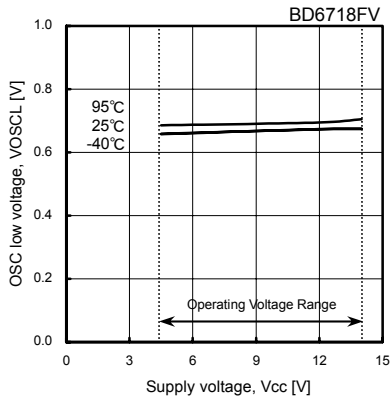


Fig.25 OSC low voltage

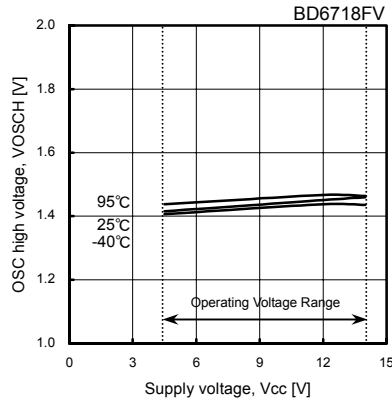


Fig.26 OSC high voltage

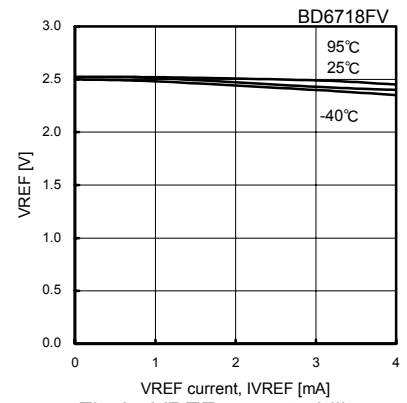


Fig.27 VREF current ability

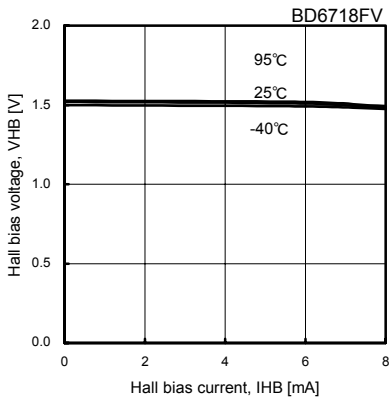


Fig.28 Hall bias current ability

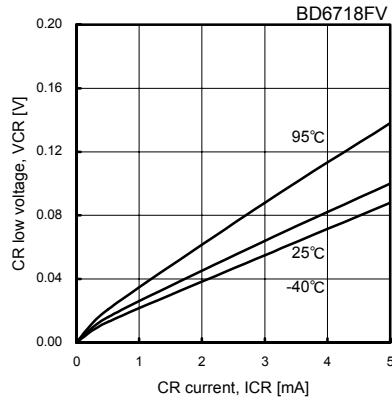


Fig.29 CR output low voltage

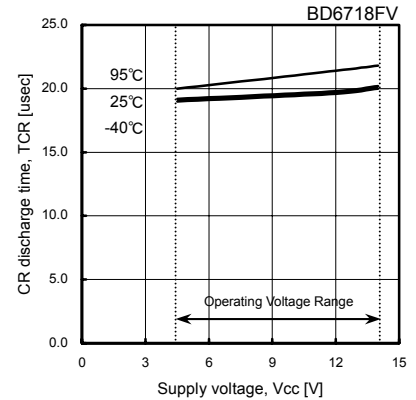


Fig.30 CR discharge time

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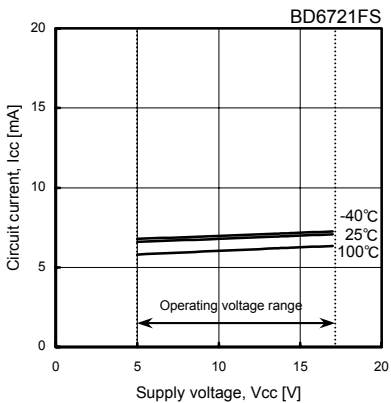


Fig.31 Circuit current

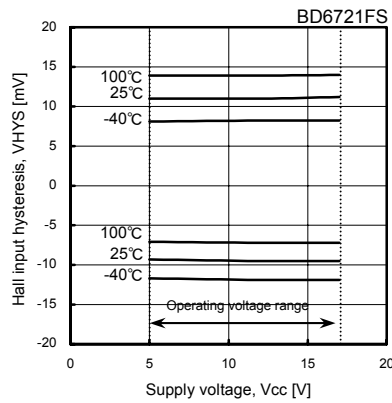


Fig.32 Hall input hysteresis

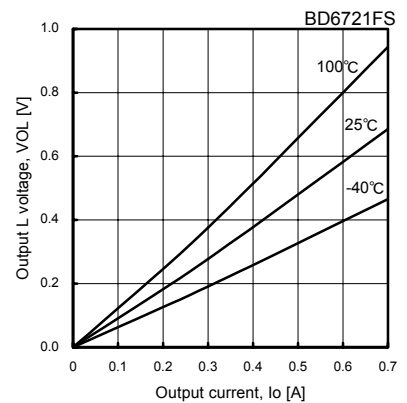


Fig.33 Output low voltage (Temperature characteristics)

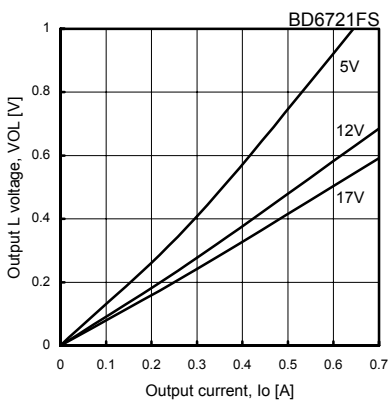


Fig.34 Output low voltage (Voltage characteristics)

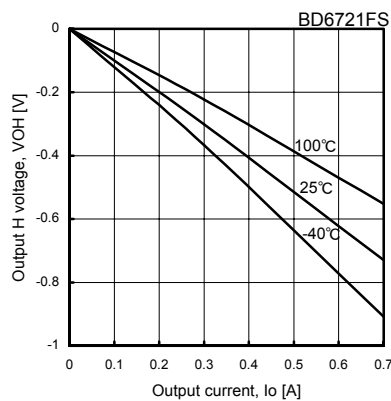


Fig.35 Output high voltage (Temperature characteristics)

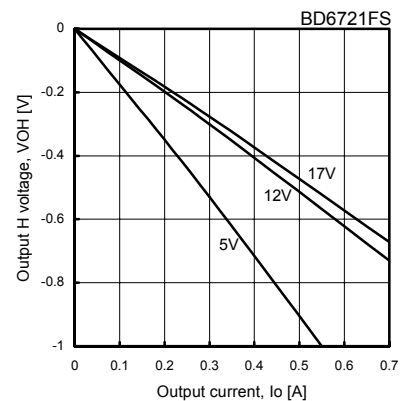


Fig.36 Output high voltage (Voltage characteristics)

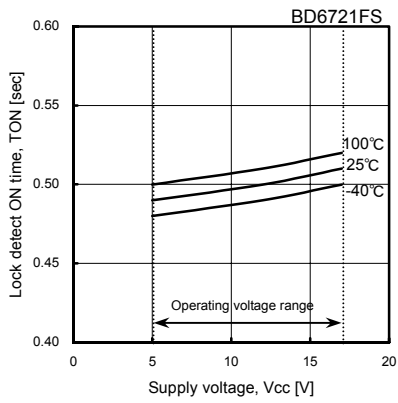


Fig.37 Lock detection ON time

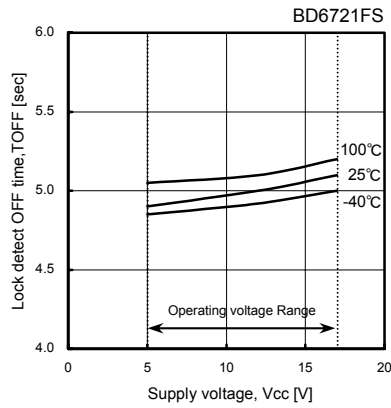


Fig.38 Lock detection OFF time

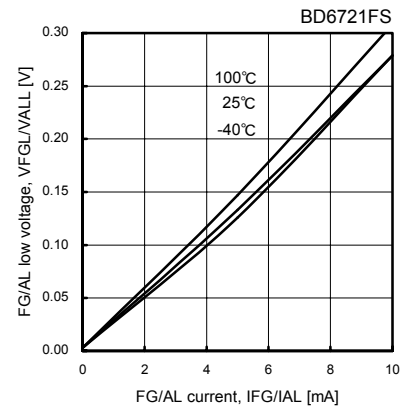


Fig.39 FG/AL low voltage (Temperature characteristics)

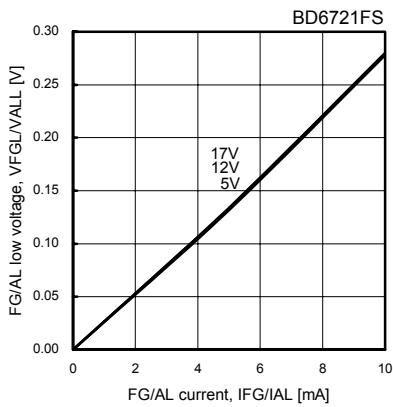


Fig.40 FG/AL low voltage (Voltage characteristics)

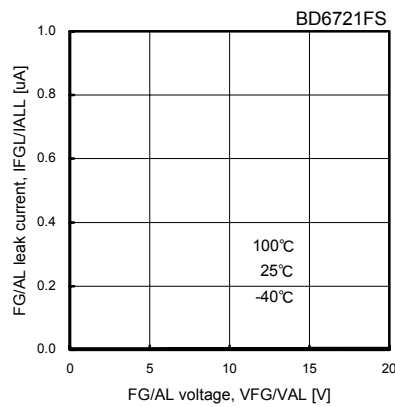


Fig.41 FG/AL leak current

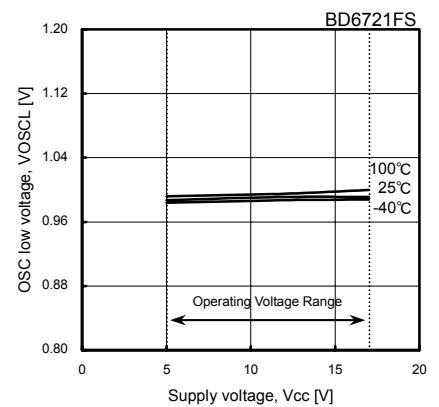


Fig.42 OSC low voltage

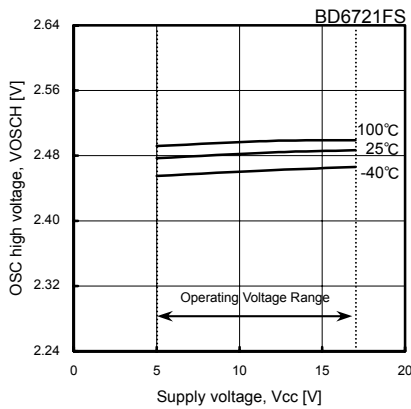


Fig.43 OSC high voltage

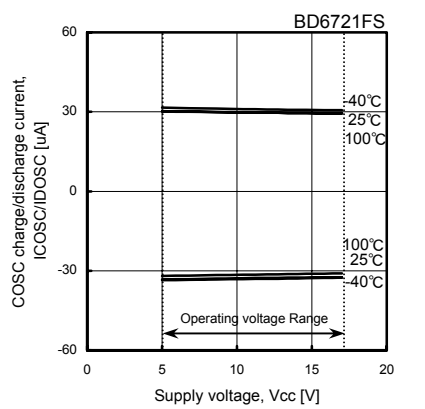


Fig.44 OSC charge discharge current

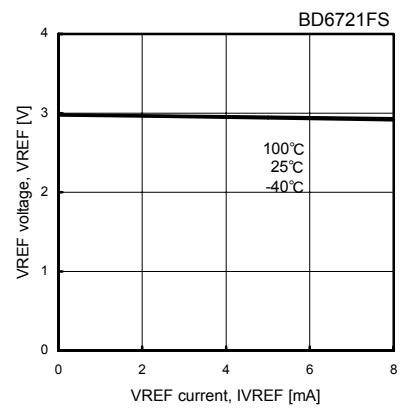


Fig.45 VREF current ability

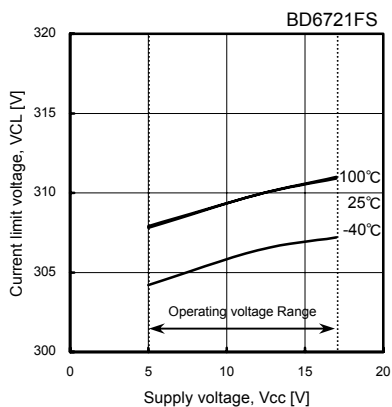


Fig.46 Current limit voltage

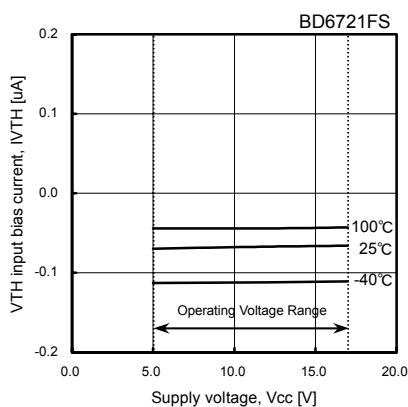


Fig.47 VTH input bias current

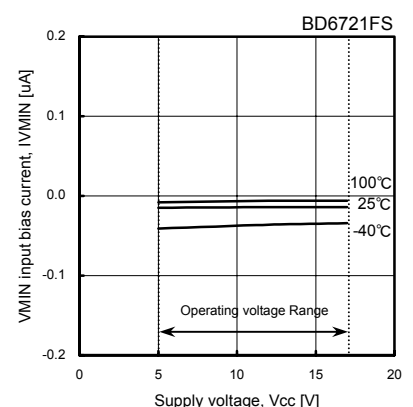


Fig.48 VMIN input bias current

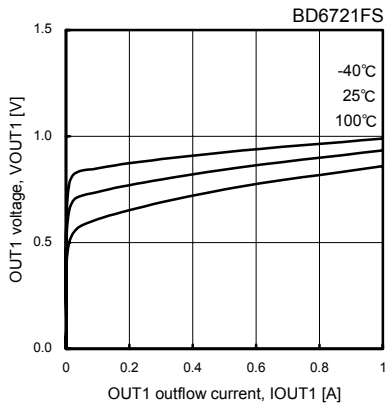


Fig.49 Low side output Body Di characteristics

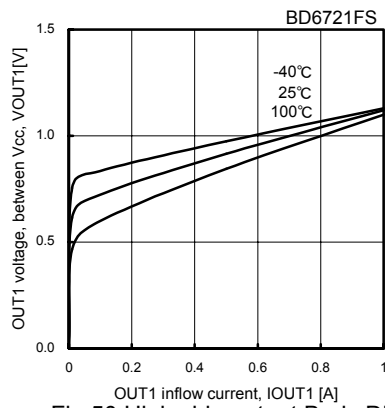


Fig.50 High side output Body Di characteristics

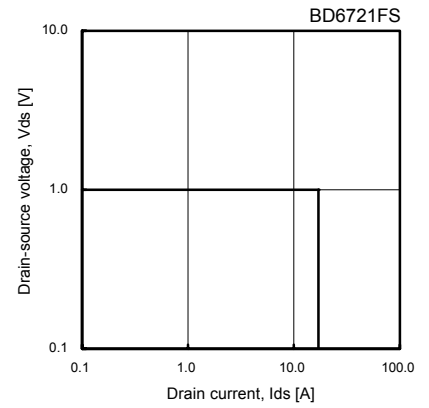


Fig.51 Output Tr ASO (upper and lower total) (TON=100msec)

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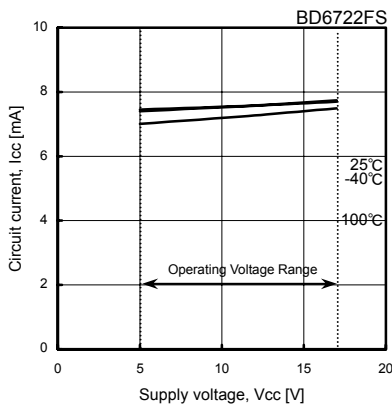


Fig.52 Circuit current

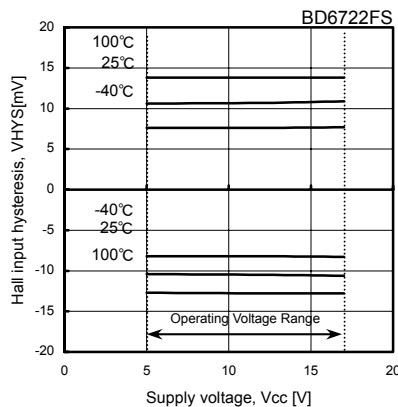


Fig.53 Hall input hysteresis

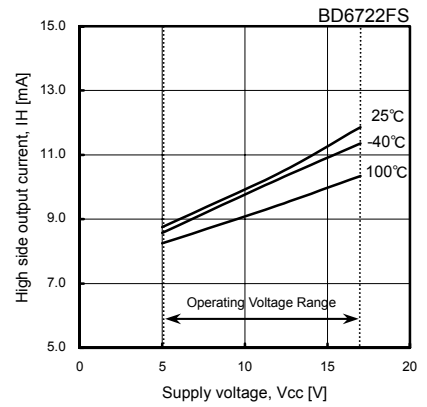


Fig.54 High side output current

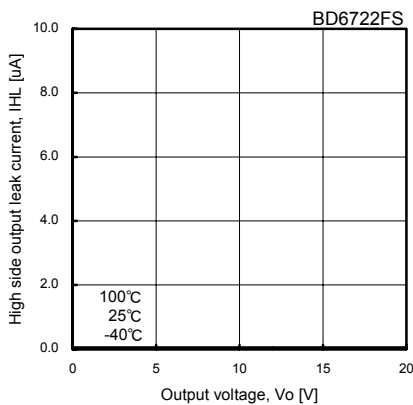


Fig.55 High side output leak current (Temperature characteristics)

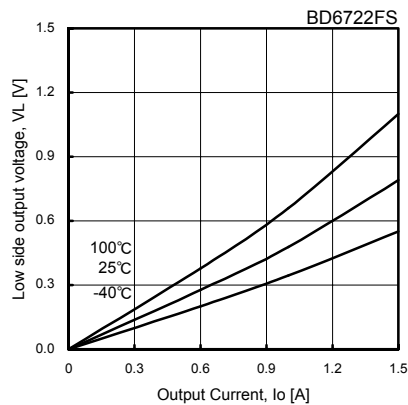


Fig.56 Low side output voltage (Voltage characteristics)

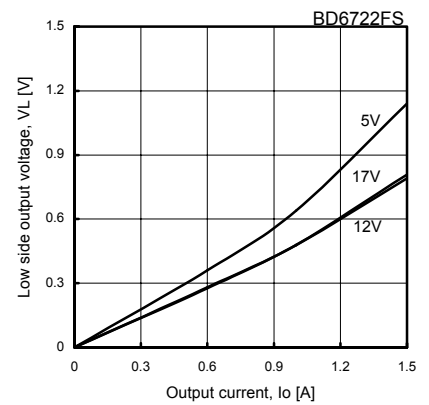


Fig.57 Low side output voltage (Voltage characteristics)

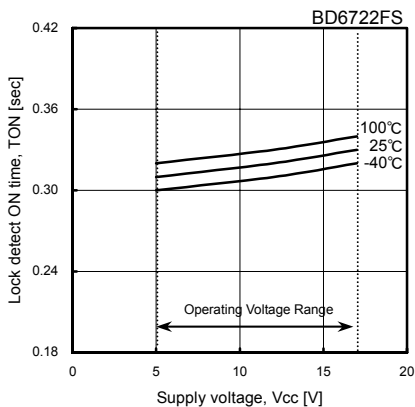


Fig.58 Lock detection ON time

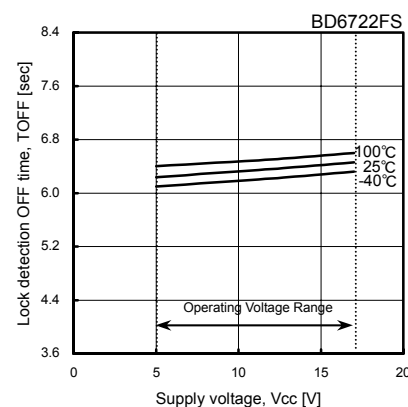


Fig.59 Lock detection OFF time

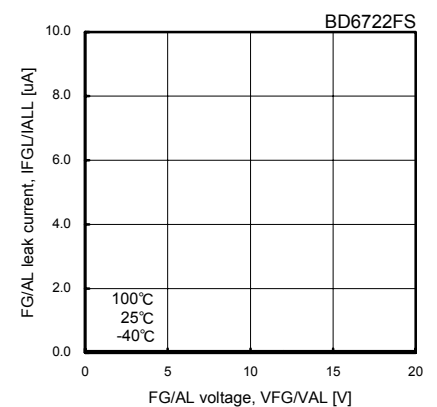


Fig.60 FG/AL leak current

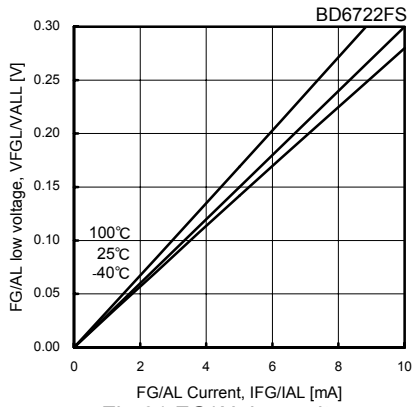


Fig.61 FG/AL low voltage (Temperature characteristics)

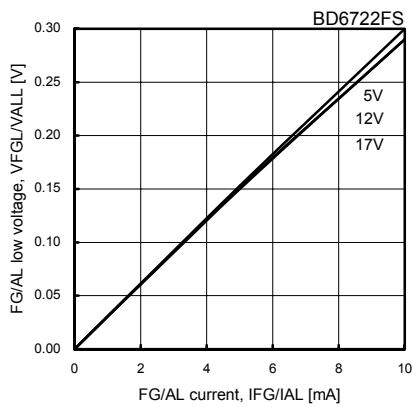


Fig.62 FG/AL low voltage (Voltage characteristics)

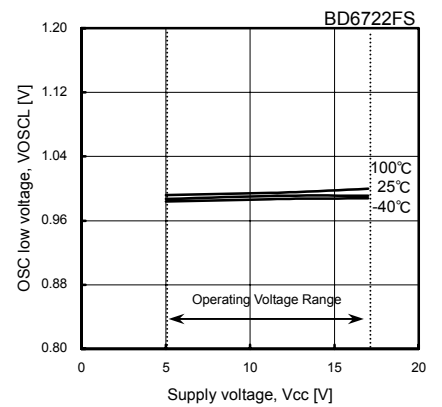


Fig.63 OSC low voltage (Voltage characteristics)

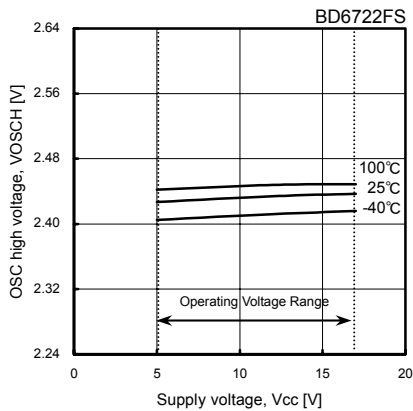


Fig.64 OSC high voltage (Voltage characteristics)

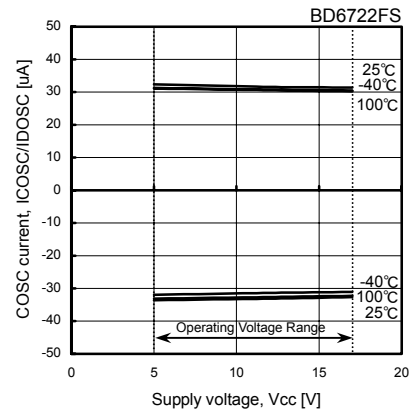


Fig.65 OSC charge discharge current (Voltage characteristics)

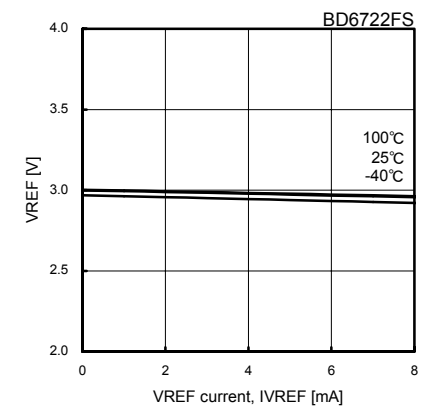


Fig.66 VREF current ability (Temperature characteristics)

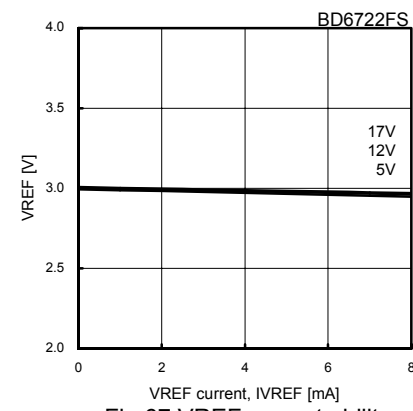


Fig.67 VREF current ability (Voltage characteristics)

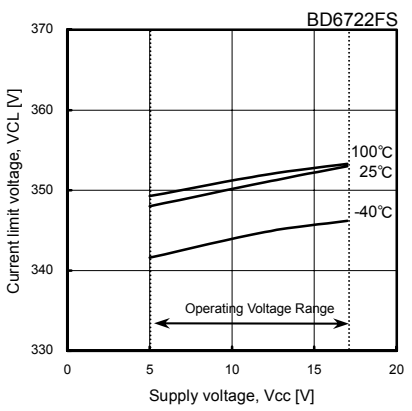


Fig.68 Current limit voltage (Voltage characteristics)

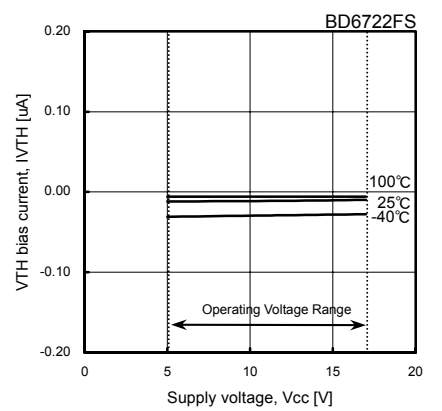


Fig.69 VTH input bias current (Voltage characteristics)

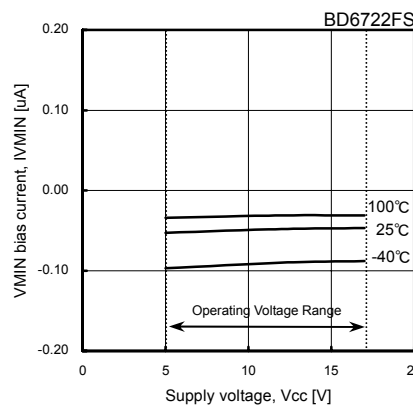


Fig.70 VMIN input bias current (Voltage characteristics)

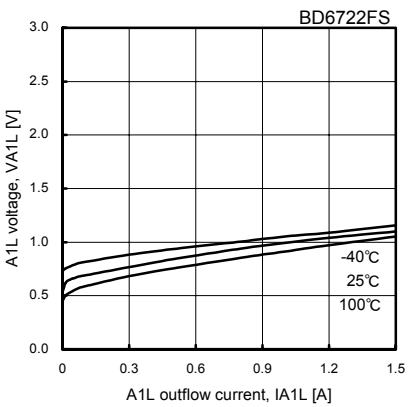


Fig.71 Low side output Body Di characteristics (Voltage characteristics)

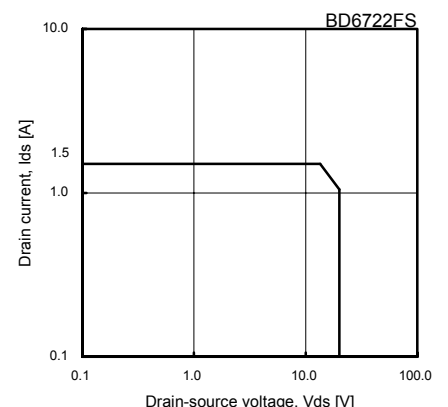


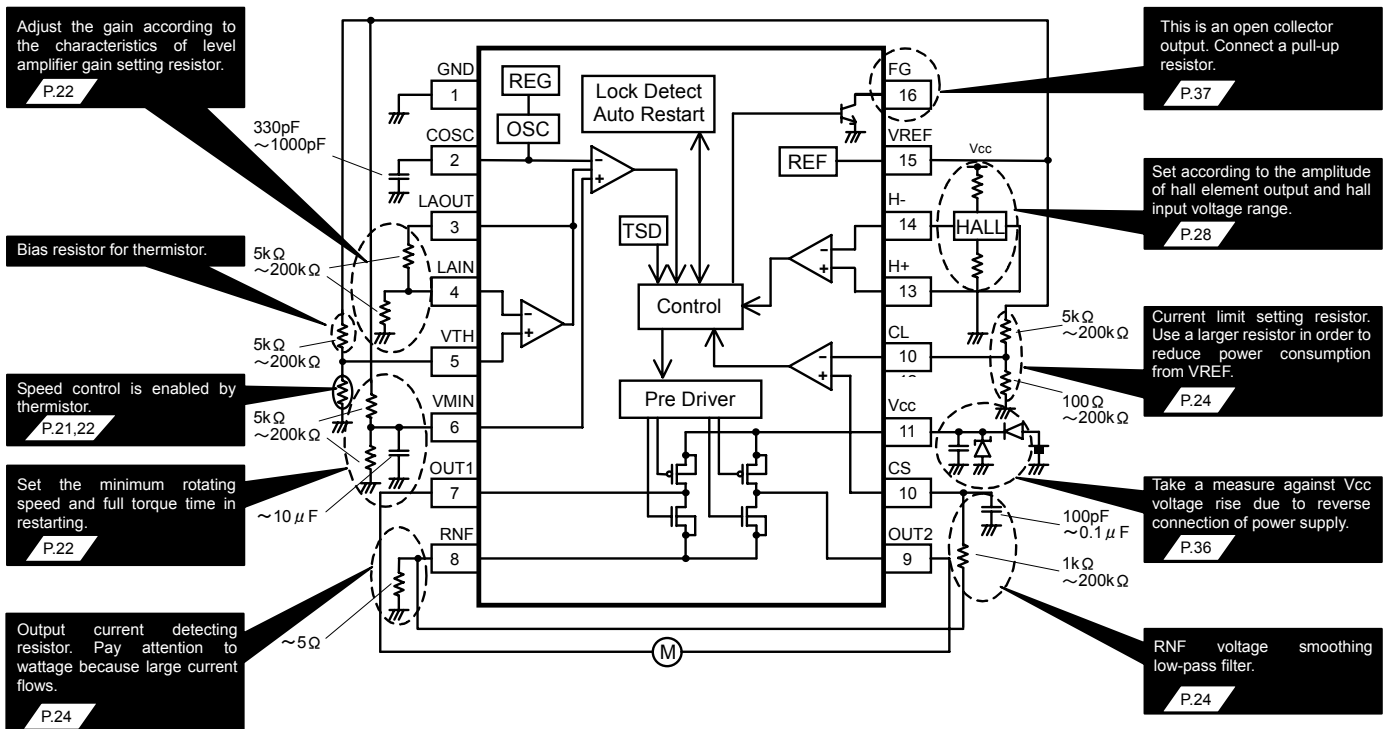
Fig.72 Low side output Tr ASO (TON=100msec) (Voltage characteristics)

●Block diagram, application circuit, and pin assignment(Constant etc are for reference)

◎BD6709FS

1) DC input application

The example of an application for rotation speed control by thermistor.



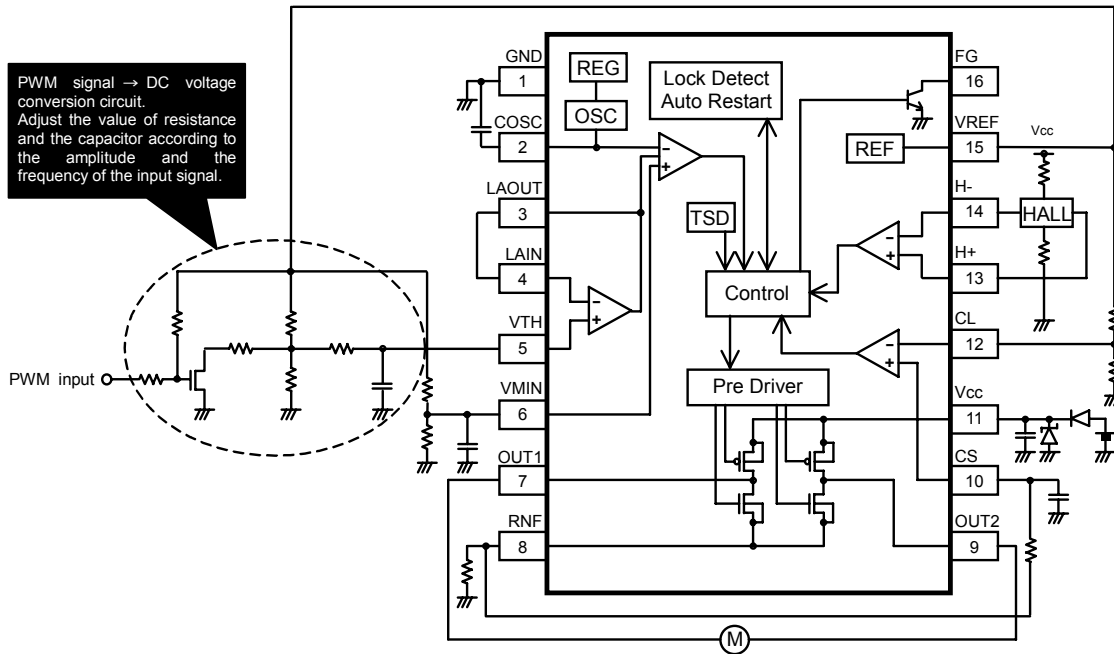
REG : Internal reference voltage OSC : Oscillation circuit REF : Reference voltage generating circuit

TSD : Thermal shutdown(heat rejection circuit)

| PIN No. | Terminal name | Function | PIN No. | Terminal name | Function |
|---------|---------------|--|---------|---------------|---|
| 1 | GND | GND terminal | 9 | OUT2 | Motor output terminal 2 |
| 2 | COSC | Oscillating capacitor connecting terminal | 10 | CS | Output current detecting terminal |
| 3 | LAOUT | Level amplifier output terminal (for setting speed control gain) | 11 | Vcc | Power supply terminal |
| 4 | LAIN | Level amplifier input terminal (for setting speed control gain) | 12 | CL | Current limiting input terminal |
| 5 | VTH | Variable speed input terminal (thermistor connecting terminal) | 13 | H+ | Hall input terminal + |
| 6 | VMIN | Minimum rotating speed setting terminal | 14 | H- | Hall input terminal - |
| 7 | OUT1 | Motor output terminal 1 | 15 | VREF | Reference voltage terminal |
| 8 | RNF | Output current detecting resistor connecting terminal (motor GND terminal) | 16 | FG | Rotating speed pulse signal output terminal |

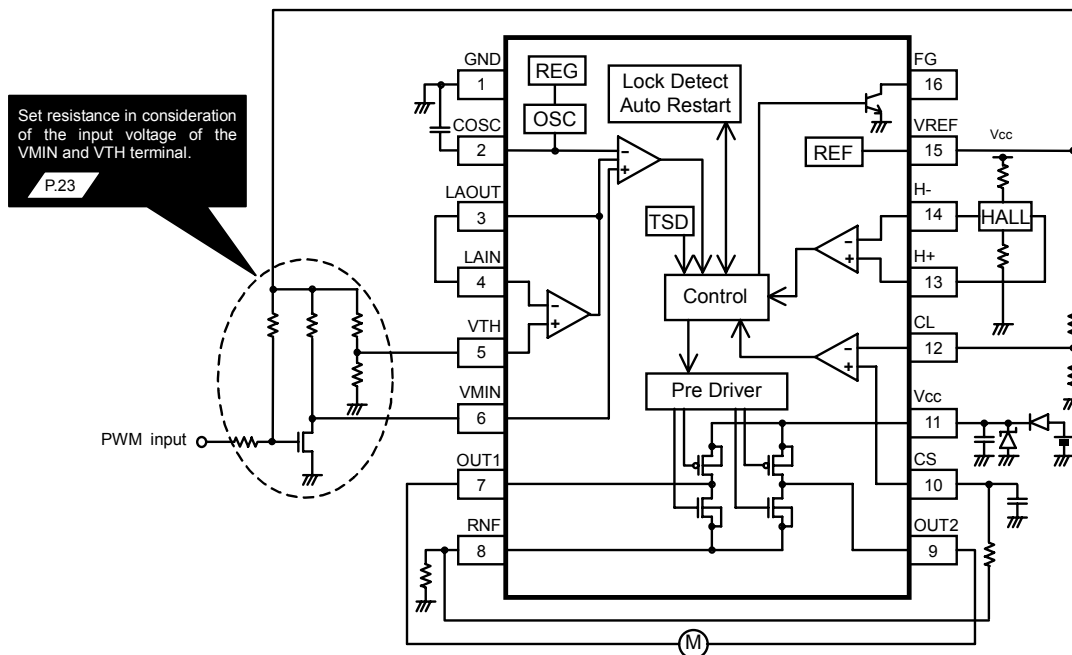
2) Pulse input application 1

The example of an application for converting external PWM signal into the DC voltage, and controlling the rotational speed. Minimum rotational speed can be set.



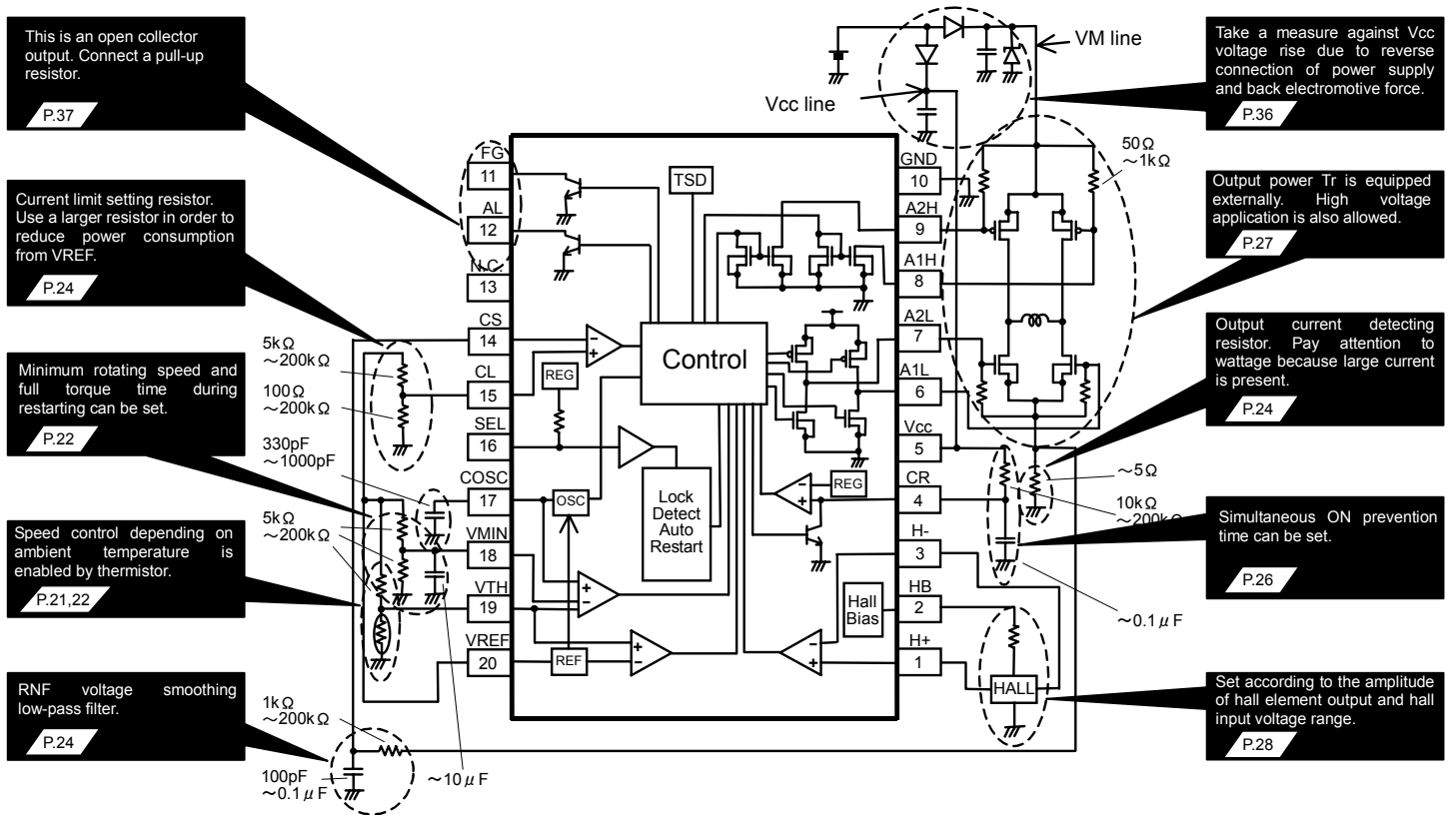
3) Pulse input application 2

The example of an application for controlling the rotational speed by DUTY of external PWM signal. The minimum rotational speed cannot be set.



1) DC input application

The example of an application for rotation speed control by thermistor.

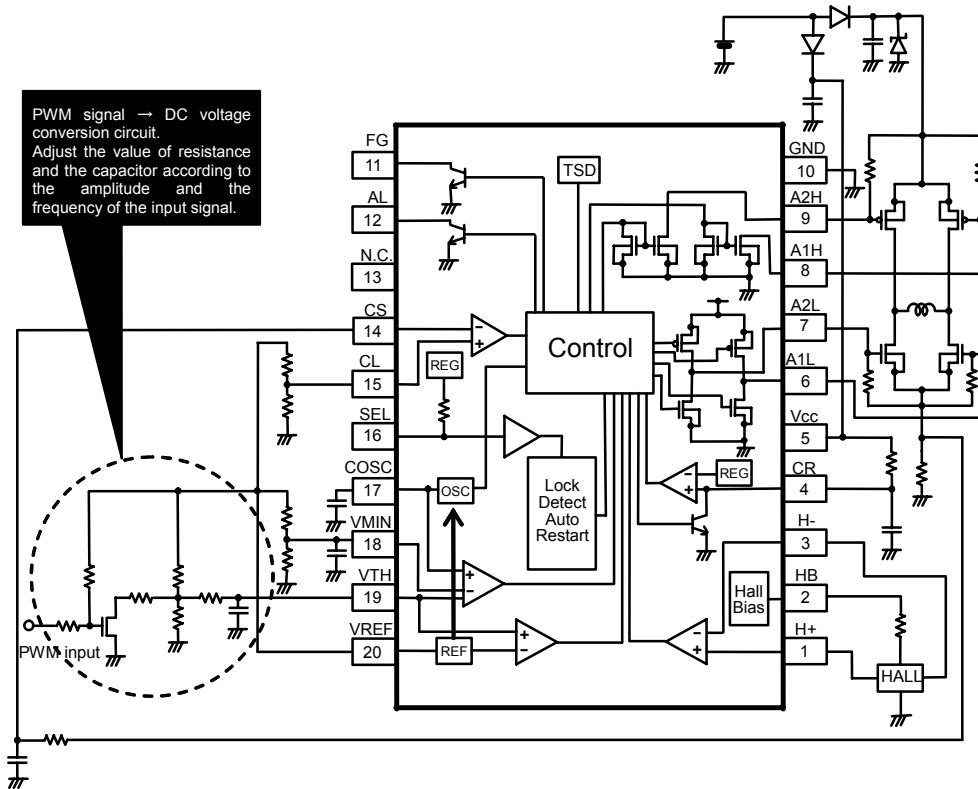


REG : Internal reference voltage OSC : Oscillation circuit REF : Reference voltage generating circuit
 TSD : Thermal shutdown(heat rejection circuit)

| PIN No. | Terminal name | Function | PIN No. | Terminal name | Function |
|---------|---------------|---|---------|---------------|--|
| 1 | H+ | Hall input terminal + | 11 | FG | Rotating speed pulse signal output terminal |
| 2 | HB | Hall bias terminal | 12 | AL | Lock alarm signal output terminal |
| 3 | H- | Hall input terminal - | 13 | N.C. | |
| 4 | CR | Charging and discharging pulse circuit capacitor and resistor connecting terminal | 14 | CS | Output current detecting terminal |
| 5 | Vcc | Power supply terminal | 15 | CL | Current limiting input terminal |
| 6 | A1L | Low side output terminal (OUT1) | 16 | SEL | Lock detection ON:OFF ratio selecting terminal |
| 7 | A2L | Low side output terminal (OUT2) | 17 | COSC | Oscillating capacitor connecting terminal |
| 8 | A1H | High side output terminal (OUT1) | 18 | VMIN | Minimum rotating speed setting terminal |
| 9 | A2H | High side output terminal (OUT2) | 19 | VTH | Variable speed input terminal (thermistor connecting terminal) |
| 10 | GND | GND terminal | 20 | VREF | Reference voltage terminal |

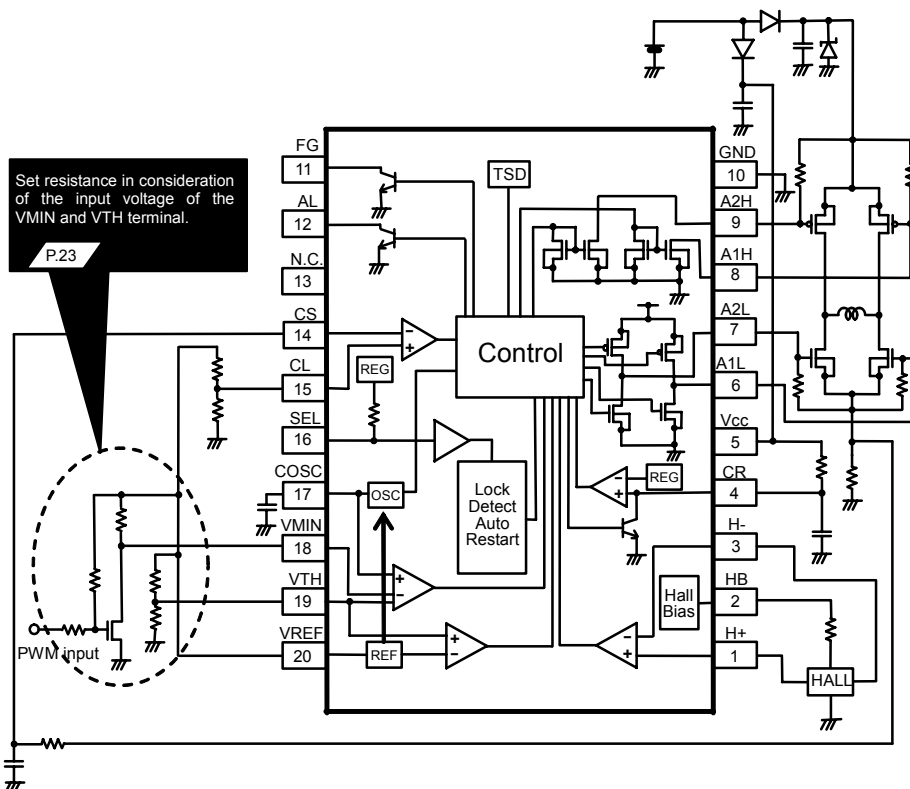
2) Pulse input application 1

The example of an application for converting external PWM signal into the DC voltage, and controlling the rotational speed. Minimum rotational speed can be set.



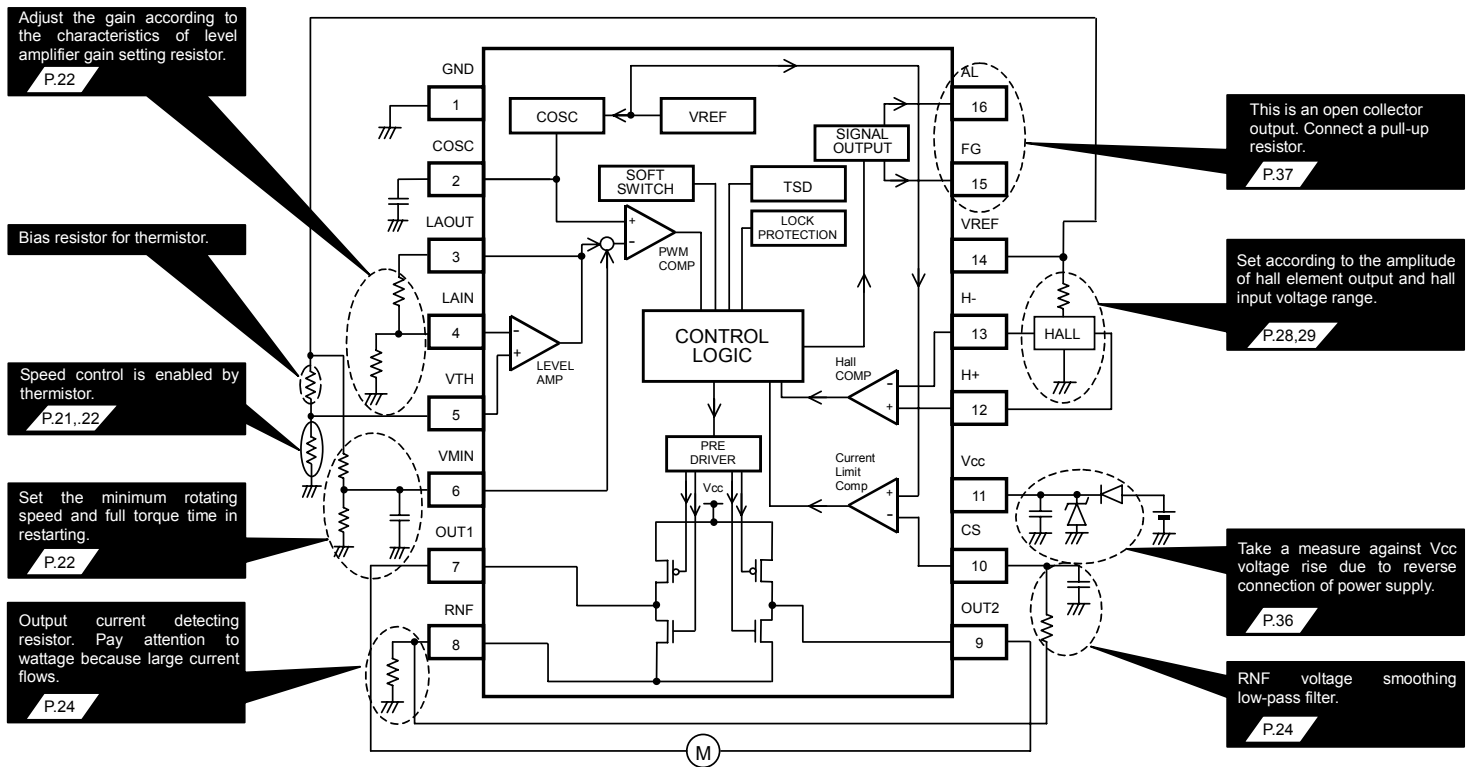
3) Pulse input application 2

The example of an application for controlling the rotational speed by DUTY of external PWM signal. The minimum rotational speed cannot be set.



1) DC input application

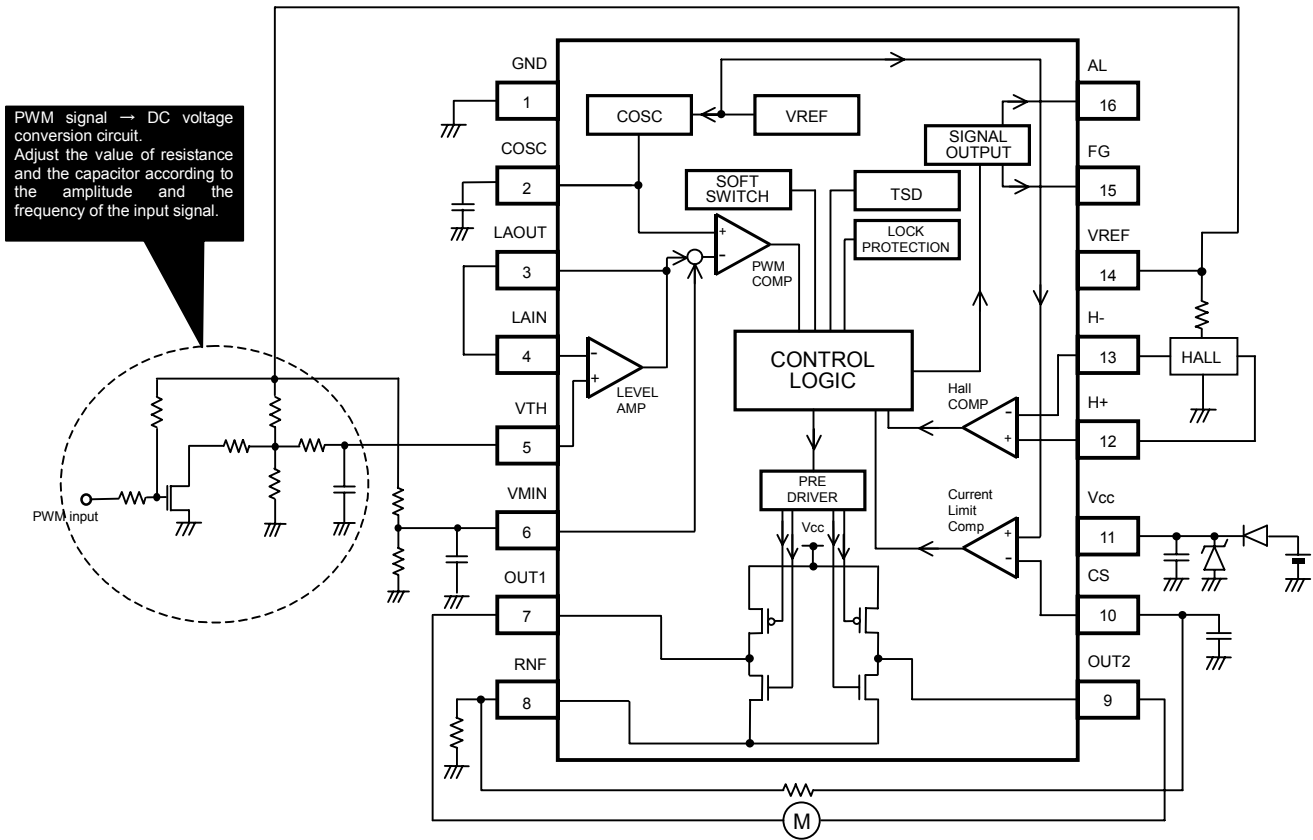
The example of an application for rotation speed control by thermistor.



| PIN No. | Terminal name | Function | PIN No. | Terminal name | Function |
|---------|---------------|--|---------|---------------|---|
| 1 | GND | GND terminal | 9 | OUT2 | Motor output terminal 2 |
| 2 | COSC | Oscillating capacitor connecting terminal | 10 | CS | Output current detecting terminal |
| 3 | LAOUT | Level amplifier output terminal (for setting speed control gain) | 11 | Vcc | Power supply terminal |
| 4 | LAIN | Level amplifier input terminal (for setting speed control gain) | 12 | H+ | Hall input terminal + |
| 5 | VTH | Variable speed input terminal (thermistor connecting terminal) | 13 | H- | Hall input terminal - |
| 6 | VMIN | Minimum rotating speed setting terminal | 14 | VREF | Reference voltage terminal |
| 7 | OUT1 | Motor output terminal 1 | 15 | FG | Rotating speed pulse signal output terminal |
| 8 | RNF | Output current detecting resistor connecting terminal (motor GND terminal) | 16 | AL | Lock alarm signal output terminal |

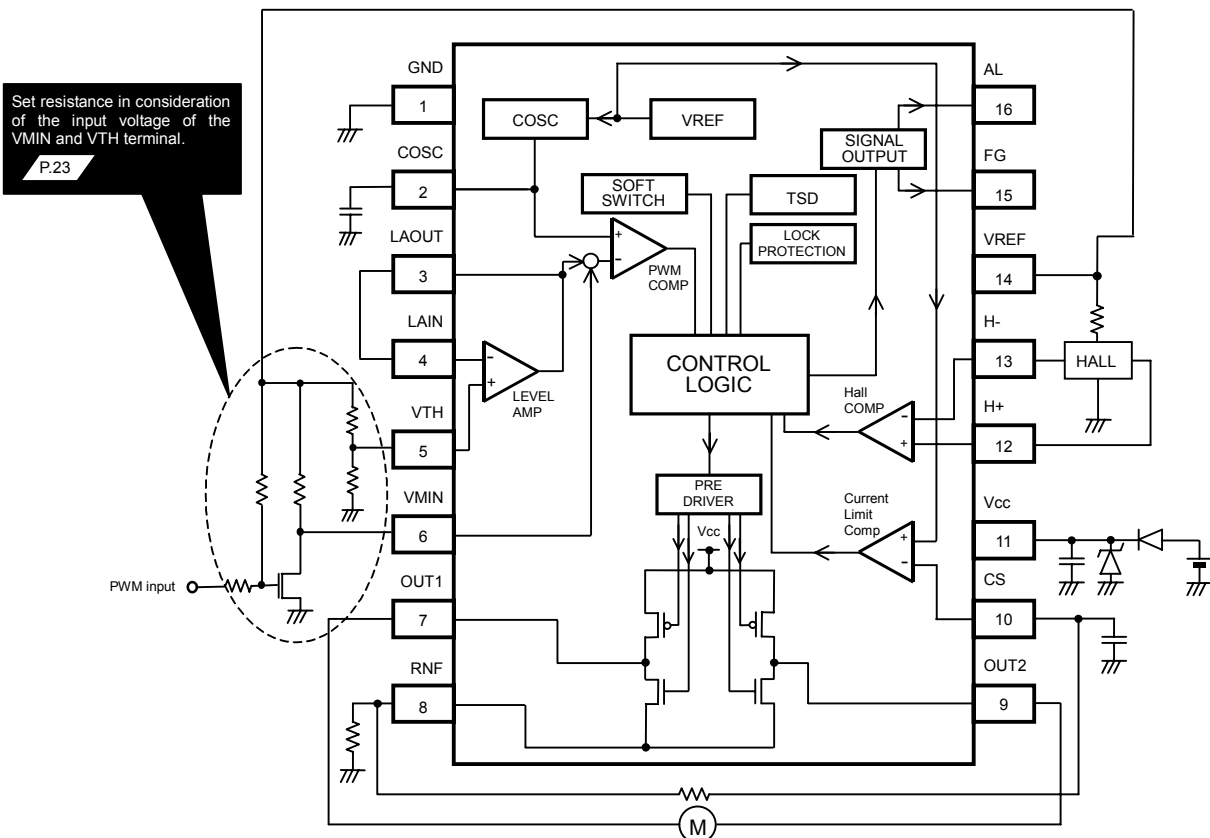
2) Pulse input application 1

The example of an application for converting external PWM signal into the DC voltage, and controlling the rotational speed. Minimum rotational speed can be set.



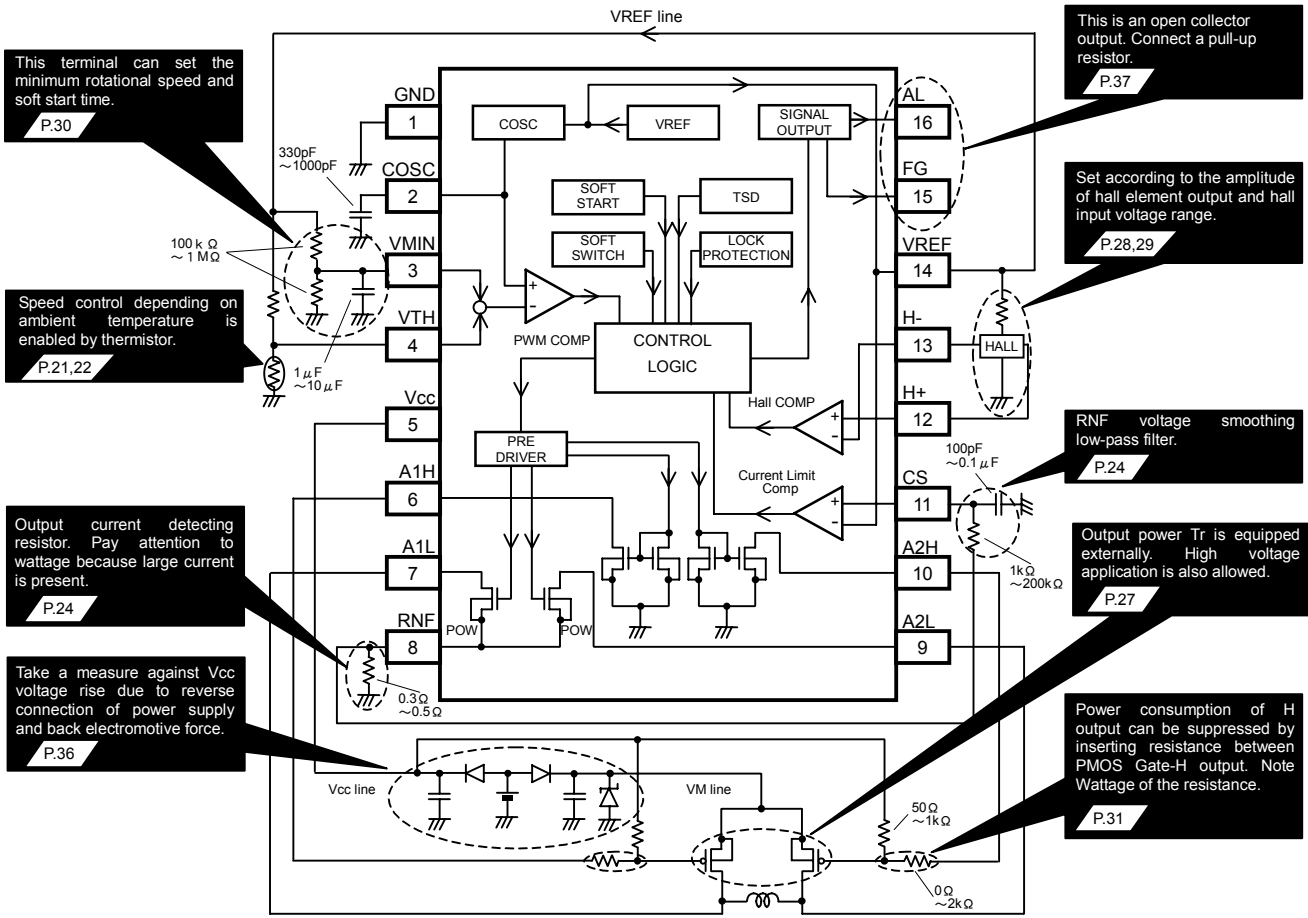
3) Pulse input application 2

The example of an application for controlling the rotational speed by DUTY of external PWM signal. The minimum rotational speed cannot be set.



1) DC input application

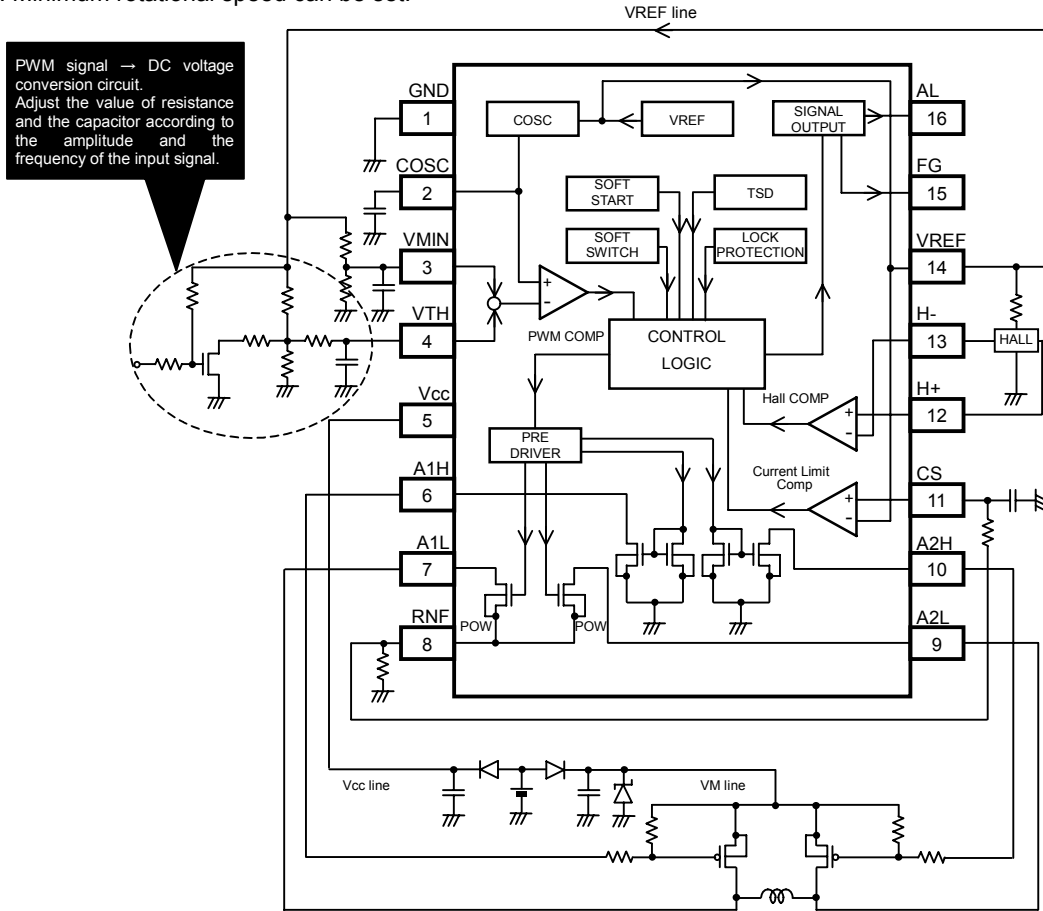
The example of an application for rotation speed control by thermistor.



| PIN No. | Terminal name | Function | PIN No. | Terminal name | Function |
|---------|---------------|--|---------|---------------|---|
| 1 | GND | GND terminal | 9 | A2L | Low side output terminal (OUT2) |
| 2 | COSC | Oscillating capacitor connecting terminal | 10 | A2H | High side output terminal (OUT2) |
| 3 | VMIN | Minimum rotating speed setting terminal | 11 | CS | Current limiting input terminal |
| 4 | VTH | Variable speed input terminal (thermistor connecting terminal) | 12 | H+ | Hall input terminal + |
| 5 | Vcc | Power supply terminal | 13 | H- | Hall input terminal - |
| 6 | A1H | High side output terminal (OUT1) | 14 | VREF | Reference voltage terminal |
| 7 | A1L | Low side output terminal (OUT1) | 15 | FG | Rotating speed pulse signal output terminal |
| 8 | RNF | Output current detecting resistor connecting terminal (motor GND terminal) | 16 | AL | Lock alarm signal output terminal |

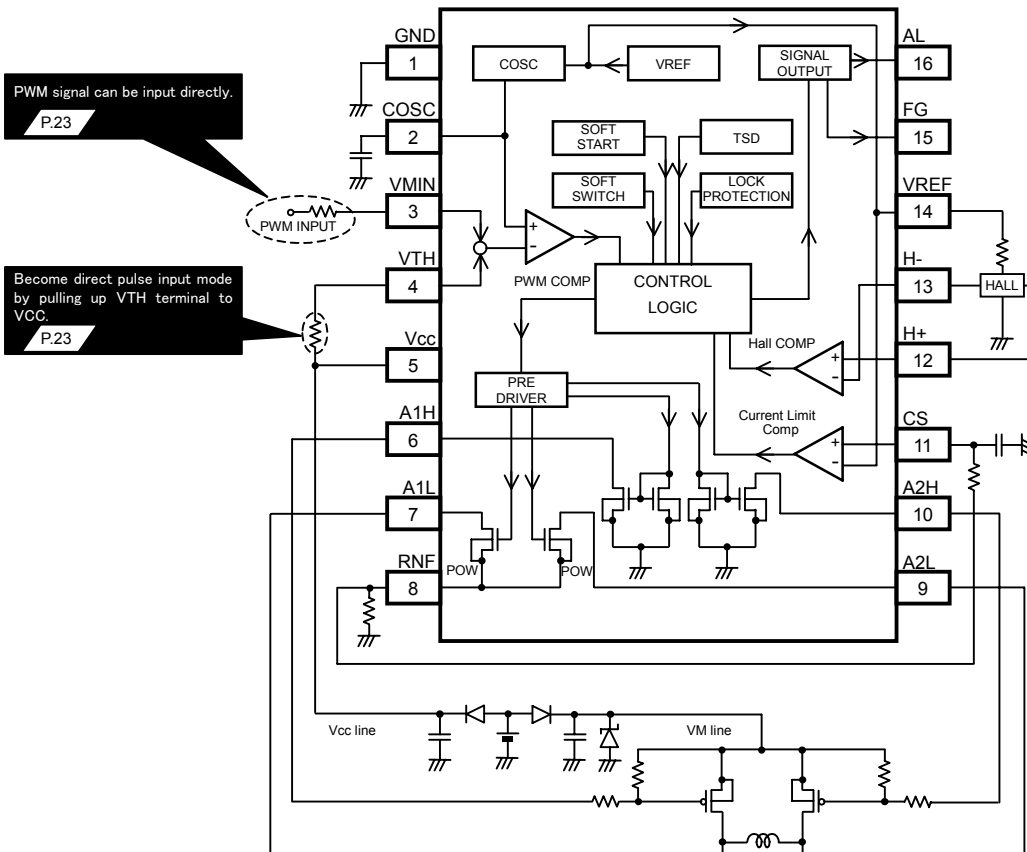
2) Pulse input application 1

The example of an application for converting external PWM signal into the DC voltage, and controlling the rotational speed. Minimum rotational speed can be set.



3) Pulse input application 2

The example of an application for controlling the rotational speed by DUTY of external PWM signal. The minimum rotational speed cannot be set.



●Description of operations

Function table

| | | BD6709FS | BD6718FV | BD6721FS | BD6722FS | Reference page |
|--|-----------|----------|----------|----------|----------|----------------|
| Variable speed control | DC input | ○ | ○ | ○ | ○ | P.21,22 |
| | PWM input | ○ | ○ | ○ | ○ | P.23 |
| Current limit | | ○ | ○ | ○ | ○ | P.24 |
| Lock protection and automatic restart | | ○ | ○ | ○ | ○ | P.25,26 |
| Output Tr simultaneous ON preventing circuit | | | ○ | | | P.26 |
| High voltage application | | | ○ | | ○ | P.27 |
| PWM soft switching | | | | ○ | ○ | P.29 |
| Soft start | | | | | ○ | P.30 |

1) Variable speed operation

Rotating speed changes by PWM ON-DUTY on the upper output.

PWM operation enables

- a) PWM operation by DC input (Method by self-oscillation connecting a capacitor to COSC terminal)
- b) PWM operation by pulse input (Method to change duty by inputting pulse directly to COSC terminal)

a) PWM operation by DC input

As shown in Fig.73, DC voltage input from LAOUT(BD6709FS, BD6721FS), or DC voltage input from VTH(BD6718FV, BD6722FS) are compared with triangle wave produced by charging and discharging current to the capacitor connected to COSC to change ON-DUTY.

Output is ON when COSC terminal voltage > VTH terminal voltage or LAOUT terminal voltage

Output is OFF when COSC terminal voltage < VTH terminal voltage of LAOUT terminal voltage

VMIN terminal is for setting the minimum rotating speed. ON-DUTY is determined by either VTH terminal voltage or LAOUT terminal voltage, whichever is lower.

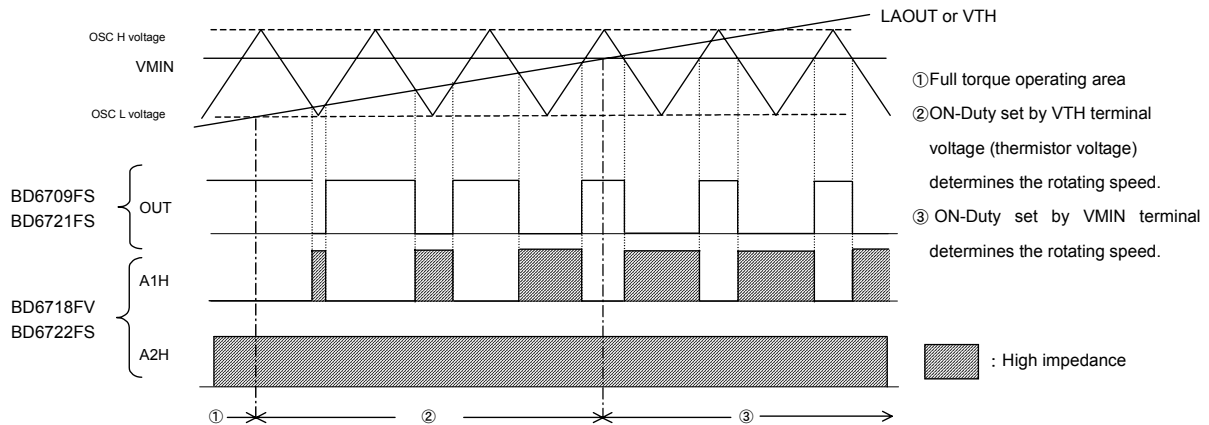


Fig.73 DC input PWM operation timing chart

COSC H and COSC L voltage is generated by dividing resistance of internal power supply, and the ratio of those voltage are designed to be hard to fluctuate.

When the input voltage at LAOUT terminal is constant, effect by fluctuation of COSCH and COSCL voltage is large. However, by setting that voltage input via VTH terminal is generated by dividing resistance of VREF terminal voltage, application can be made hard to be affected by voltage fluctuation of triangle wave. For an application which requires strict precision, determine a value with sufficient margin after full consideration of external constant is taken.

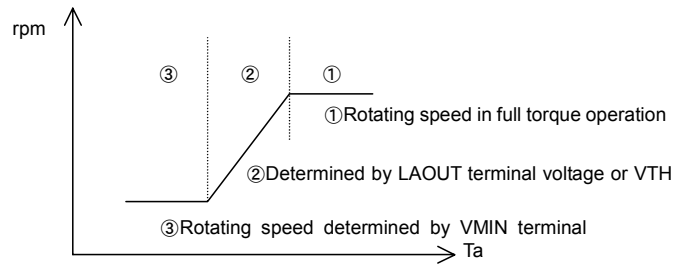


Fig.74 Setting of rotating speed

Area ① LAOUT or VTH < OSC L voltage < VMIN < OSC H voltage
 (Same as area ① in Fig.73) Rotating speed in full torque operation (ON-DUTY = 100%)

Area ② OSC L voltage < LAOUT or VTH < VMIN < OSC H voltage
 (Same as area ② in Fig.73) Rotating speed is determined by ON-DUTY set by LAOUT terminal voltage or VTH terminal voltage.

Area ③ OSC L voltage < VMIN < LAOUT or VTH < OSC H voltage
 (Same as area ③ in Fig.73) Rotating speed is determined by ON-DUTY set by VMIN terminal voltage.
 The motor can be stopped by setting OSC H voltage < VMIN (ON-DUTY = 0%).

Assuming that VTH thermistor resistor is open, when VTH terminal voltage is above VREF, full torque operation is performed.

○Level amplifier <BD6709FS, BD6721FS>

Level amplifier amplifies the voltage of VTH by the ratio of resistor connected to LAOUT and LAIN to be output to LAOUT.

In the case of Fig.75, LAOUT = (10k + 20k)/10k × VTH, and the input voltage at VTH terminal is approximately tripled.

Furthermore, when VTH terminal voltage need not be amplified, LAOUT and LAIN should be shorted as shown in Fig.76. VTH terminal voltage equals to LAOUT terminal voltage.

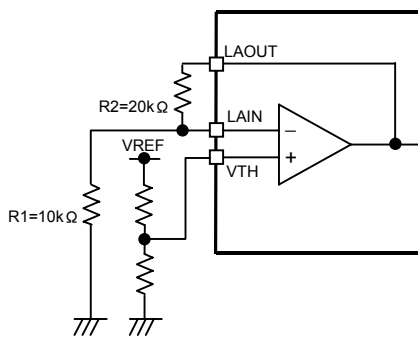


Fig.75 Level amplifier application

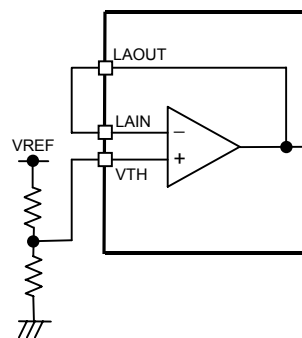


Fig.76 Level amplifier application 2

○Restart from lock protecting operation <BD6709FS, BD6718FV, BD6722FS>

When restarting from lock protection operation, VMIN becomes L so that the motor restarts in full torque.

The time for reaching full torque is determined by resistor R1 and capacitor C1 connected to VMIN terminal as shown in Fig.77.

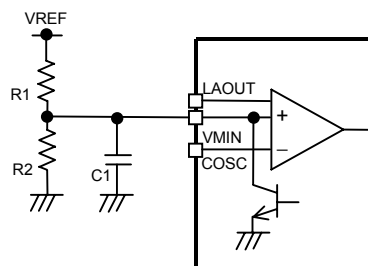


Fig.77 Restart from lock protection (DC input)

b) PWM operation by pulse input <BD6709FS, BD6718FV, BD6721FS>

Pulse signal can be input to VMIN terminal for PWM operation as shown in Fig.78.

The ratio of ON-DUTY of the output changes by the cycle of the input pulse signal as shown in Fig.79.

Set the voltage of the terminal VTH as $V_{REF} > V_{TH} > V_{OSCH}$.

Set the voltage input to the VMIN terminal

H level : $V_{REF} > V_{MIN} > V_{OSCH}$

L level : $V_{OSCL} > V_{MIN}$

as shown in Fig.79.

Output is ON in H logic of external PWM signal and OFF in L logic.

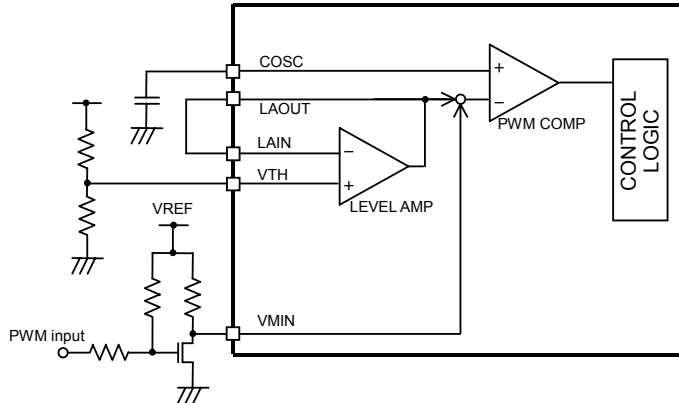


Fig.78 Direct control by DUTY of external PWM

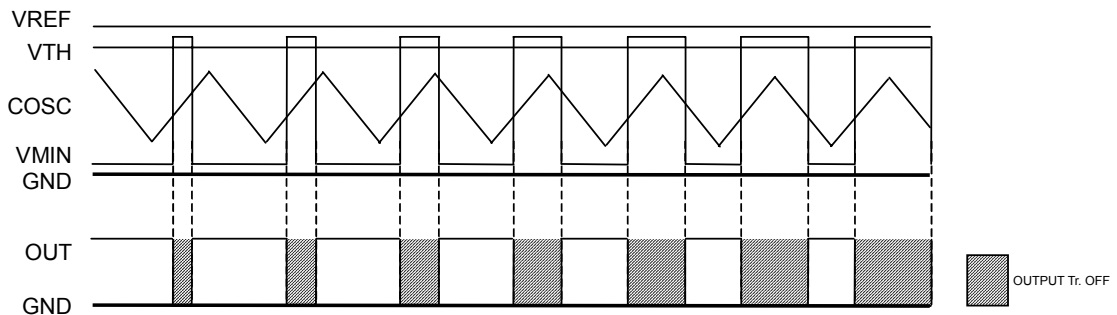


Fig.79 VTH, VMIN input voltage and output PWM timing chart in pulse input mode

b-2) PWM operation by pulse input <BD6722FS>

By pulling up VTH(4PIN) to Vcc as shown in Fig.80, the output can operate in PWM by inputting the pulse signal directly to VMIN(6PIN). However, adjust the value of R2 to become $V_{TH} = 15V$ at $V_{CC} \geq 15V$ so that the voltage of the terminal VTH should not exceed 15V.

The ratio of ON-DUTY of the output changes by the cycle of the input pulse signal as shown in Fig.81.

Set the voltage input to the VMIN terminal

H level : $V_{CC} - 2.0V > V_{MIN} > V_{OSCH}$

L level : $V_{OSCL} > V_{MIN}$

as shown in Fig.81.

Output is ON in H logic of external PWM signal and OFF in L logic.

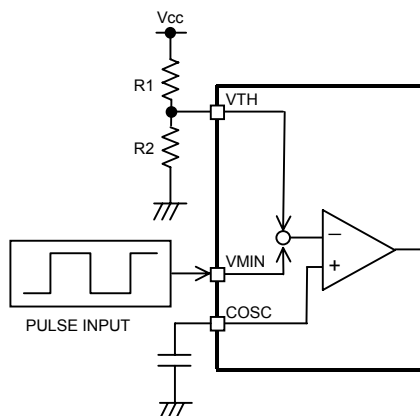


Fig.80 External PWM signal input

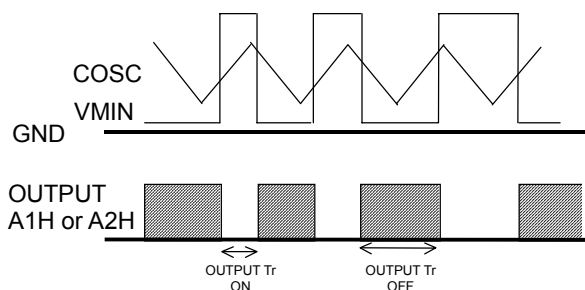


Fig.81 Pulse input operation timing chart

2) Current limit (current limiting circuit)

The current limit circuit turns off the output, when the current that flows to the motor coil is detected exceeding a set value.

The current value that current limit operates is determined by

- Voltage of CL terminal and voltage of RNF terminal (BD6709FS, BD6718FV)
- Internal setting voltage and voltage of RNF terminal (BD6721FS, BD6722FS)

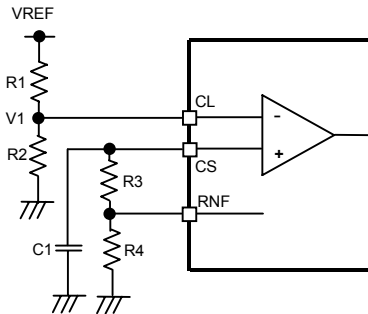


Fig.82 External setting of current limit voltage

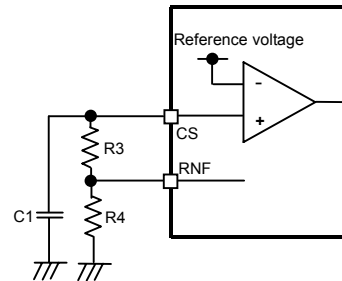


Fig.83 Internal setting of current limit voltage

- Setting according to voltage of CL terminal and RNF terminal.

For example about BD6718FV, in Fig.82

When $R1=40k\Omega$ 、 $R2=10k\Omega$ 、 $R4=0.5\Omega$, the amperage I that current limit operates is

$$V1 = \frac{R2}{R1+R2} \times VREF = \frac{10k}{40k + 10k} \times 2.5 = 0.5V$$

$$I = \frac{V1}{R4} = \frac{0.5}{0.5} = 1A$$

Current limit circuit operates at 1A.

Short CL terminal to VREF, short CS and RNF terminal to GND when the current limit function is not used.

- Setting according to internal voltage and RNF terminal.

For example about BD6722FS, in Fig.83

When $R4=0.33\Omega$, the current limit setting voltage is 350mV(typ.)

$$I = \frac{350mV}{0.33\Omega} = 1.06A$$

Current limit circuit operates at 1.06A.

Short CS and RNF terminal to GND when the current limit function is not used.

Both of a) and b)

$R3$ and $C1$ are low-pass filters for RNF smooth voltage. Adjust for a current limit not to malfunction in proportion to the PWM frequency.

Connect the capacitor with the COSC terminal to do the resume operation after a current limit operates at the PWM operation by the pulse input.

3) Lock protection and automatic restart

Motor rotation is detected by hall signal, and lock detection ON time (TON) and lock detection OFF time (TOFF) are set by the IC internal counter. Timing chart is shown in Fig.84.

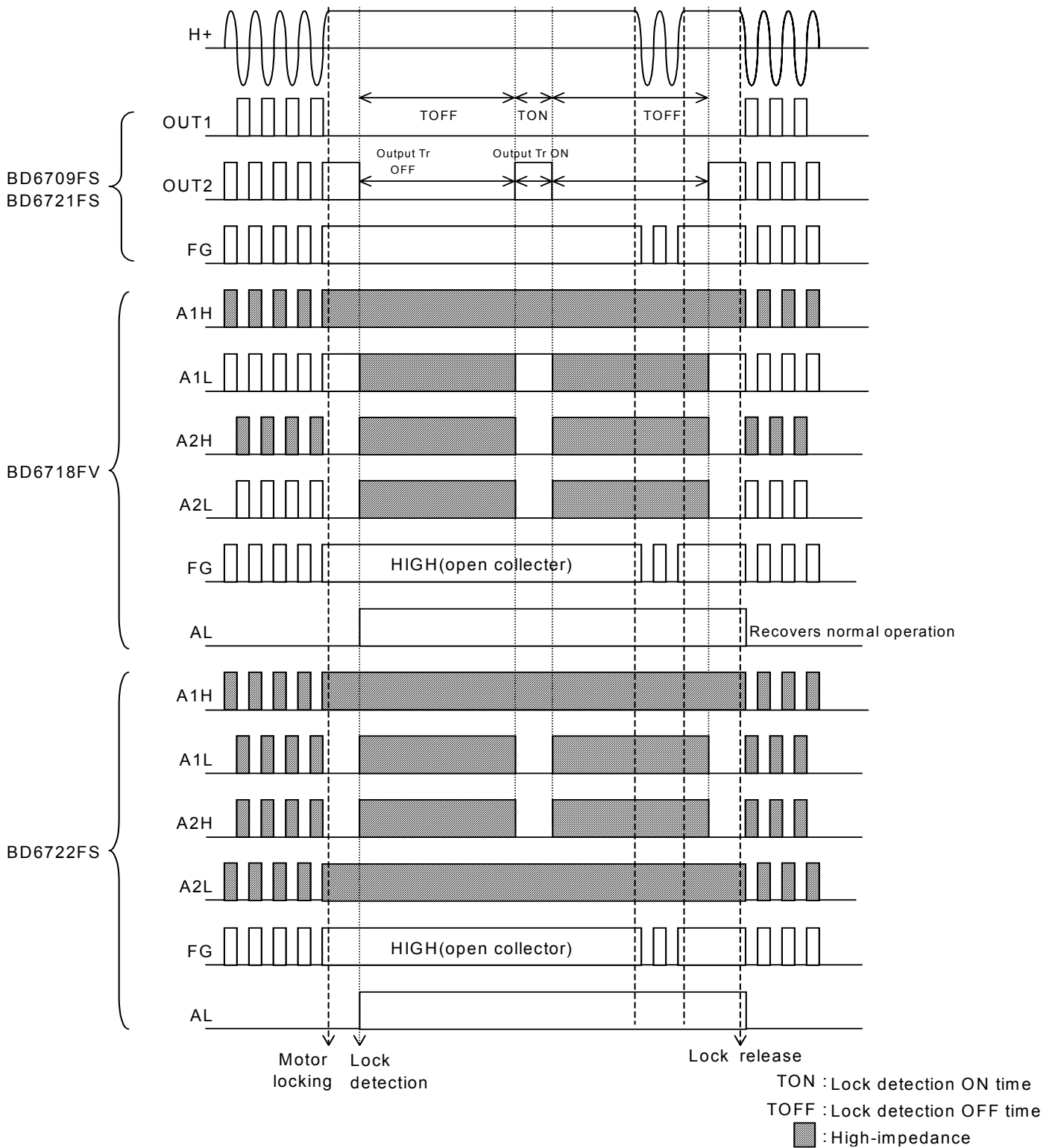


Fig.84 Lock protection (incorporated counter system) timing chart

* For BD6718FV, lock detection time (TOFF) setting can be changed by SEL terminal.
(See the electric characteristics item)

* BD6721FS, BD6722FS

When torque off logic is input by the control signal during fixed time (typ. 1ms), the lock protection function becomes off. It is not influenced at the lock protection time and it is possible to restart at once.

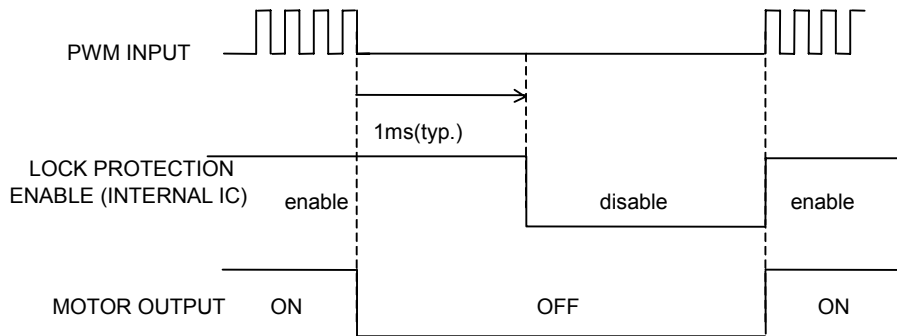


Fig.85 PWM signal and lock protection operation<BD6722FS>

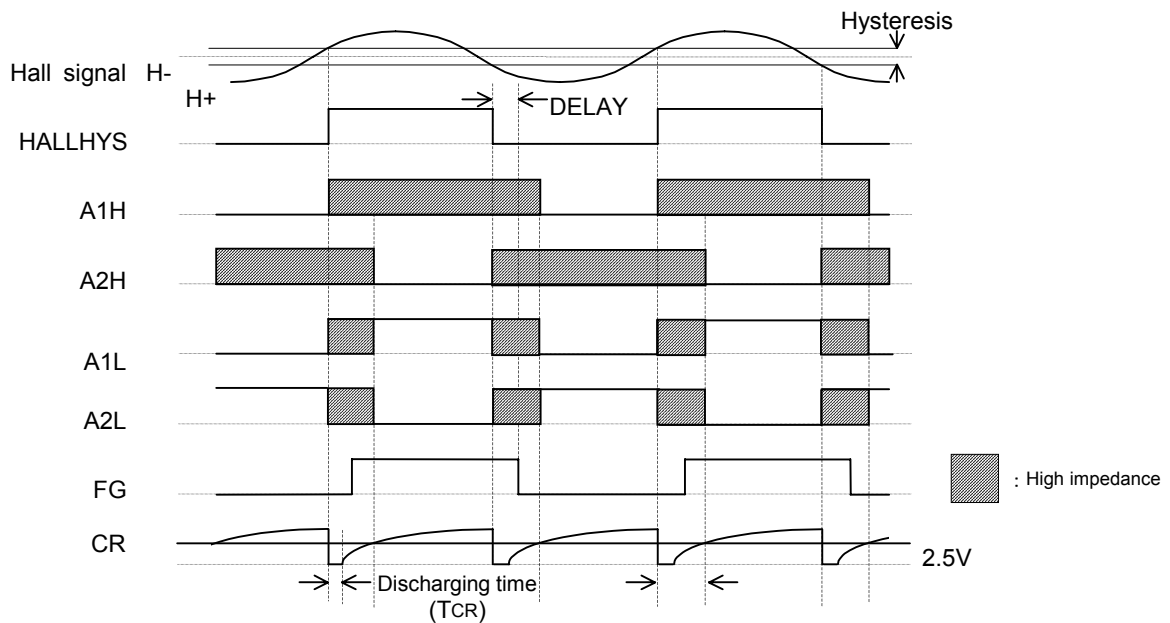
The lock protection function doesn't work in an input frequency that is slower than 1kHz(typ.) when assuming H level DUTY≒0% of the PWM input signal.

Input signal that frequency are faster than 2kHz.

4) Output Tr simultaneous ON prevention circuit <BD6718FV>

The capacitor is discharged according to the cycle of hall signal by connecting an external capacitor and resistor to CR terminal.

When CR terminal voltage is lower than internal reference voltage (2.5V:typ), IC output has a high impedance. High impedance block in output switching can be changed by changing the capacitance and resistance to be connected to CR terminal. It allows prevention of simultaneous activation, regardless of switching speed of external Tr.



5) High voltage application <BD6718FV>

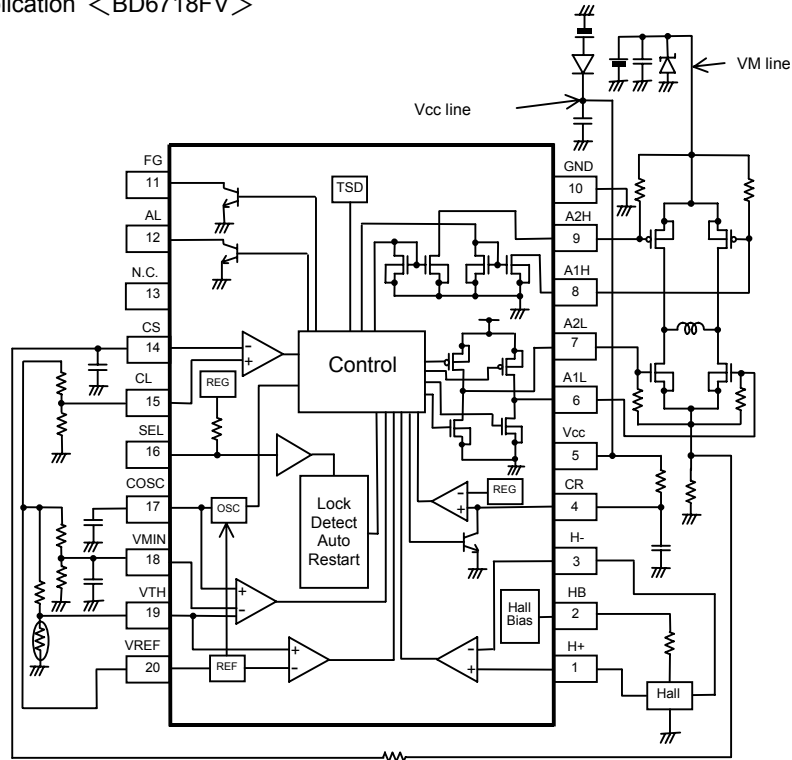


Fig.87 High voltage application (BD6718FV)

The absolute maximum rating of Vcc is 15V, while the absolute maximum rating of A1H and A2H terminal voltage is 36V. Therefore it is possible to make VM line an application with another power supply higher than 15V. To ensure the absolute maximum rating 36V of A1H and A2H terminal voltage is not exceeded, take physical measures, such as placing a Zener diode or a capacitor to create a return route of current between VM line and GND.

<BD6722FS>

The absolute maximum rating of Vcc is 20V, while the absolute maximum rating of A1H, A2H, A1L and A2L terminal voltage is 34V. Therefore it is possible to make VM line an application with another power supply higher than 20V. To ensure the absolute maximum rating 34V of A1H, A2H, A1L and A2L terminal voltage is not exceeded, take physical measures, such as placing a Zener diode or a capacitor to create a return route of current between VM line and GND.

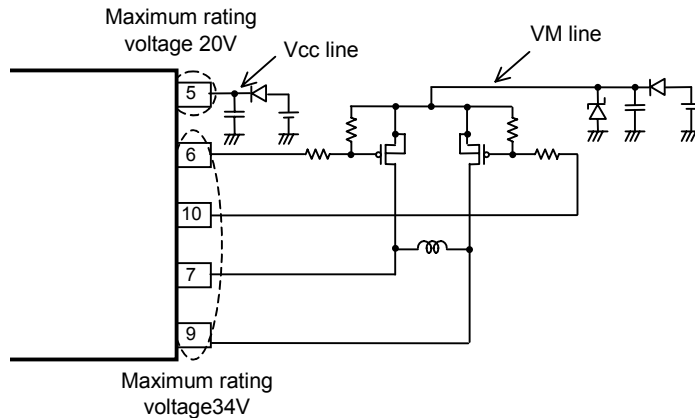


Fig.88 High voltage application (BD6722FS)

6) Hall input setting

Hall input voltage range is shown in operating conditions.

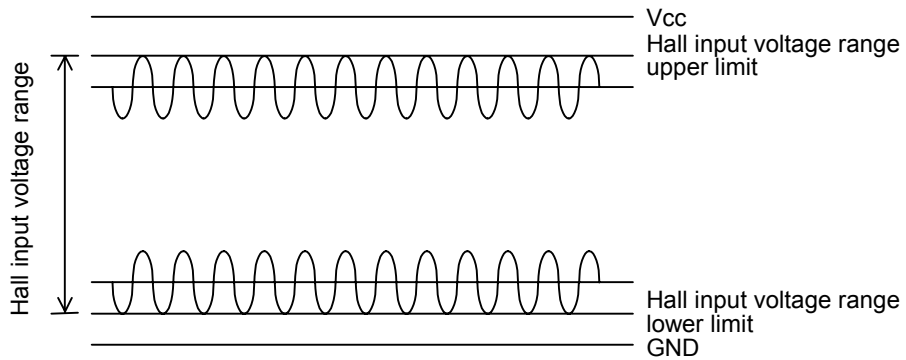


Fig.89 Hall input voltage range

Adjust the value of hall element bias resistor R1 and R2 in Fig.90 so that the input voltage of a hall amplifier is input in "hall input voltage range" including signal amplitude.

○Reducing the noise of hall signal

Hall element may be affected by Vcc noise or the like depending on the wiring pattern of board. In this case, place a capacitor like C1 in Fig.90. In addition, when wiring from the hall element output to IC hall input is long, noise may be loaded on wiring. In this case, place a capacitor like C2 in Fig.90.

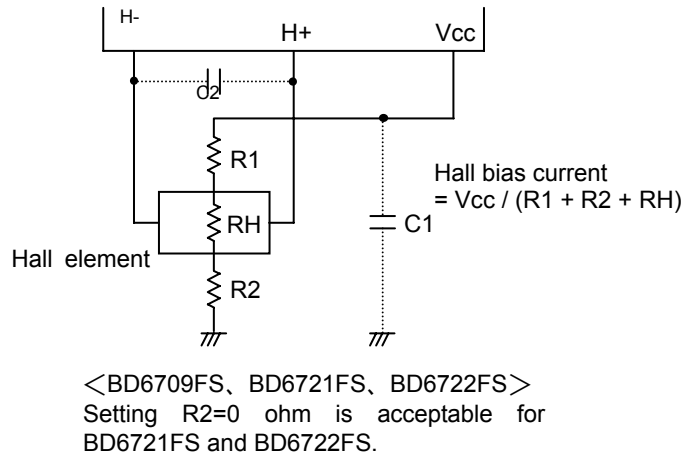
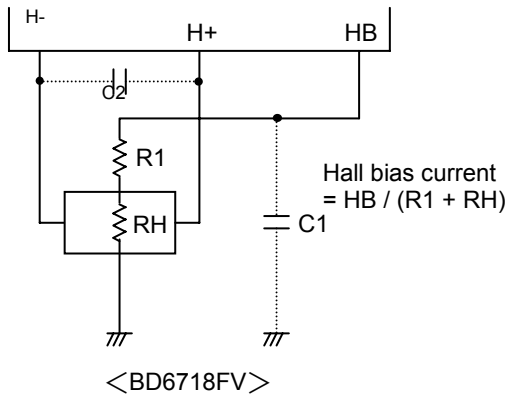


Fig.90 Application near hall signal

7) PWM soft switching<BD6721FS, BD6722FS>

The soft switching section is set to the timing before and after the change of the hall signal. The length of the soft switching section can be changed by adjusting the amplitude of the hall signal. The soft switching section becomes long if the amplitude of the hall signal is reduced, and the gradient of the output current becomes smooth. However, when a soft switching is applied too much, torque shortage might be caused. Therefore, set to the hall signal amplitude about 100mVpp that the reversely electromotive voltage is suppressed appropriately.

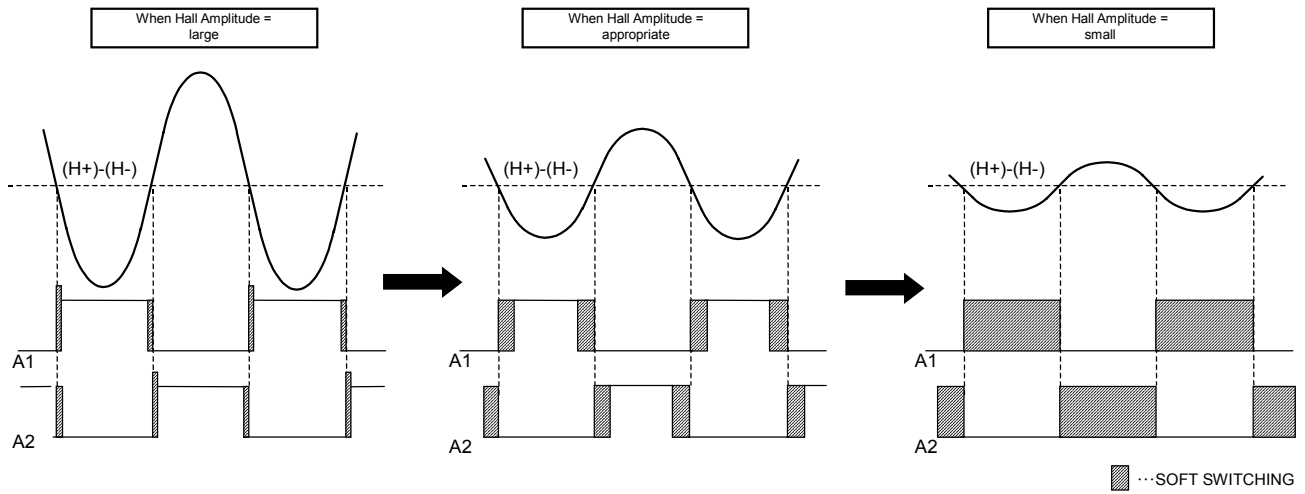


Fig.91 Relation between hall signal amplitude and output wave

The soft switching function operates in the DC input application and the pulse input application. Adjust the hall bias resistance so that the hall signal amplitude become large when you do not want to use the soft switching function.

8) Soft start<BD6722FS>

The soft start section is set at the rotation start or the LOCK protection release, etc.

The soft start time is decided by the constant circuit connected with VMIN terminal.

And VMIN terminal is used as the lowest rotational speed setting. Set VMIN to 1.75V or more (lowest rotational speed DUTY \leq 50%).

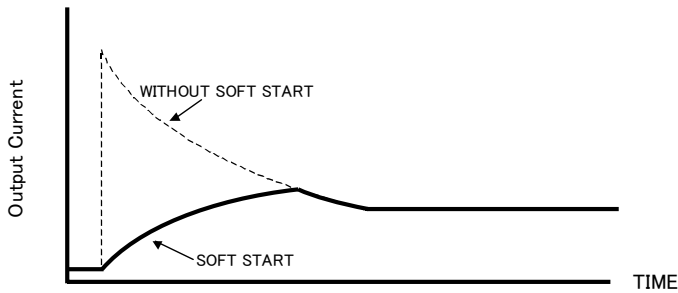


Fig.92 Output current characteristic by soft start

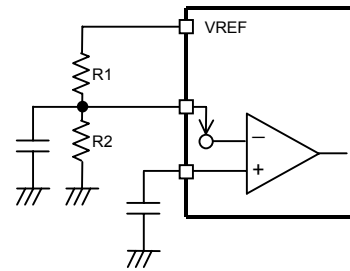


Fig.93 Soft start setting circuit

a) Soft start time of VTH setting DUTY \geq 50%

It gradually rises to the DUTY set with VTH after it starts.

Fig.94 shows the soft start operation at VTH setting DUTY=70% and VMIN setting DUTY=20%.

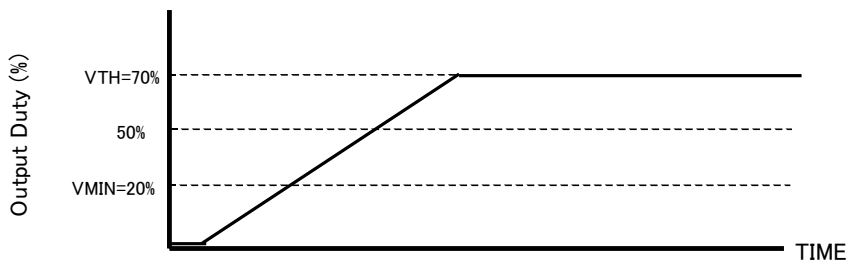


Fig.94 Soft start time chart of DUTY \geq 50%

b). Soft start time of VTH setting DUTY \leq 50%

DUTY rises gradually, and rises to Duty=50% temporarily after it starts. The purpose of this is to secure the start torque when DUTY set with VTH and VMIN is too low.

It gradually descends to the DUTY set with VTH and VMIN after it rotates by DUTY=50% for a fixed time.

Fig.95 shows the soft start operation at VTH setting DUTY=10% and VMIN setting DUTY=20%.

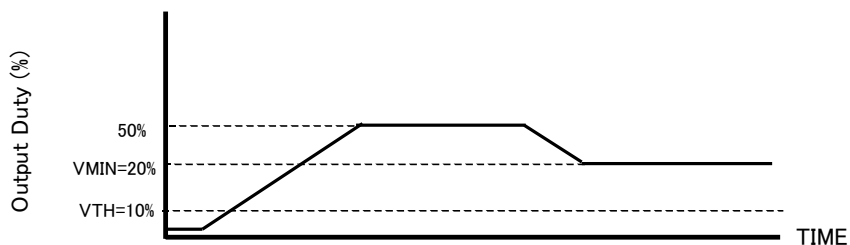


Fig.95 Soft start time chart of DUTY \leq 50%

Because the lock protection function is turned off while soft start, soft start time can be set longer than the lock detection time. The soft start function can be turned off by not connecting the capacitor to VMIN terminal.

9) The upside output of pre-driver<BD6718FV, BD6722FS>

High side output of pre-driver (half pre-driver) are constant current open-drain output. Decide the resistance of R1 so that the voltage generated between G-S of external Pch transistor may exceed enough the threshold voltage of the transistor.

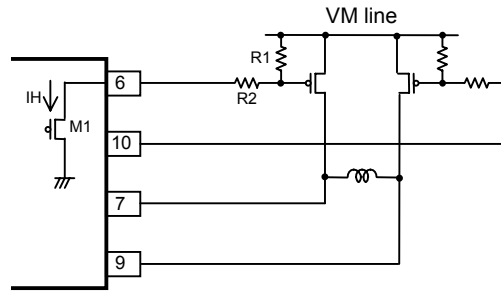


Fig.96 Voltage setting between G-S of external Pch transistor

Ex. At $R1=100\ \Omega$, V_{GSP} : between G-S of the Pch transistor.

$$\begin{aligned} V_{GSP} &= R1 \times I_H \\ &= 100\ \Omega \times 10\text{mA (typ.)} \\ &= 1\text{V} \end{aligned}$$

* R2 is used to suppress the power consumption of IC.

At $V_M = 12\text{V}$, The power consumption of upside output transistor M1 is

$$P_{M1} = \{ V_M - (R1 + R2) \times I_H \} \times I_H$$

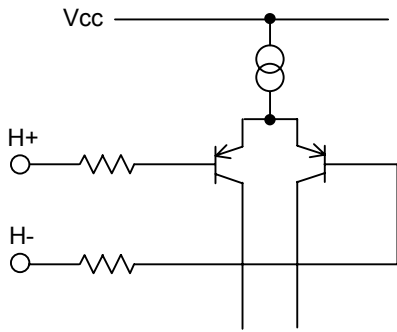
| | |
|--|-----------------------|
| At $R1 = 100\ \Omega$, $R2 = 0\ \Omega$ | $P_{M1}=110\text{mW}$ |
| At $R1 = 100\ \Omega$, $R2 = 1\text{k}\ \Omega$ | $P_{M1}=10\text{mW}$ |

Especially BD6722FS, useless power consumption in the upside output is suppressed by appropriately setting R2, and a permissible loss of the package can be used effectively in lower output.

●Equivalent circuit

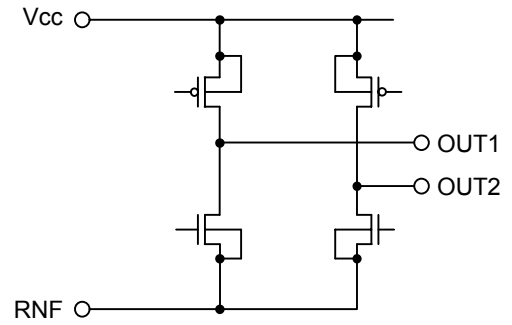
©BD6709FS

1) Hall input terminal



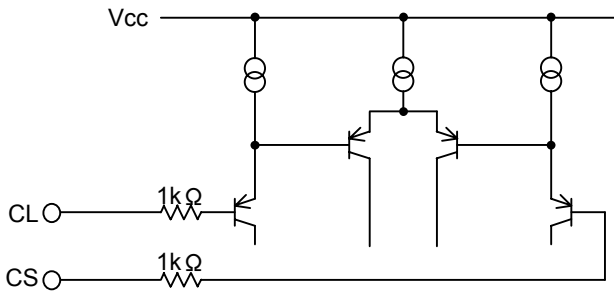
2) Motor output terminal

Output current detecting resistor connecting terminal

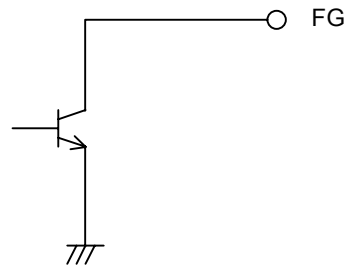


3) Current limiting input

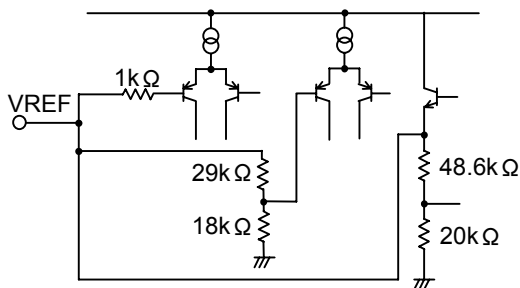
Output current detecting terminal



4) FG output terminal



5) Reference voltage terminal



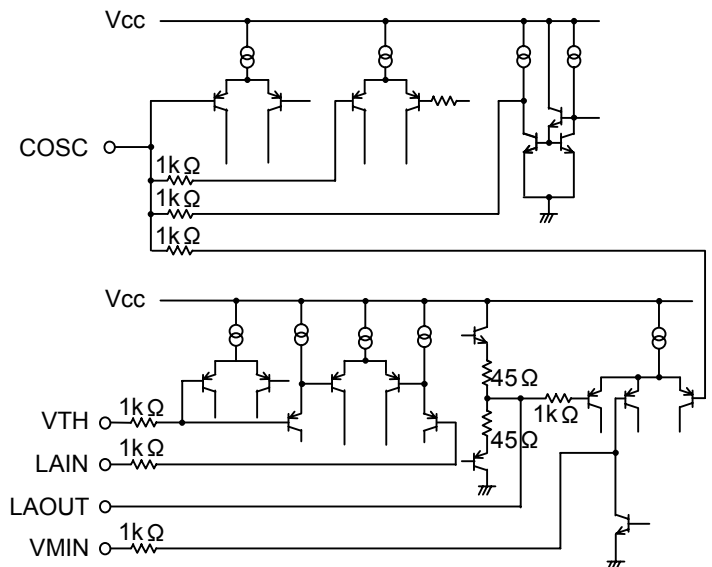
6) Oscillating capacitor connecting terminal

Variable amplifier input terminal

Level amplifier input terminal

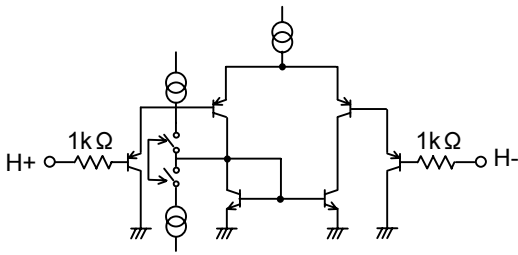
Level amplifier output terminal

Minimum rotating speed setting terminal

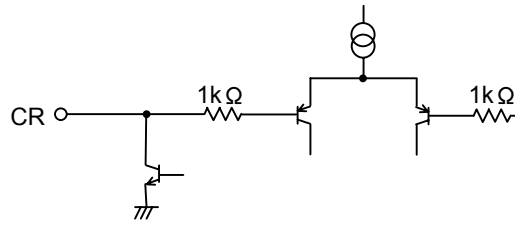


©BD6718FV

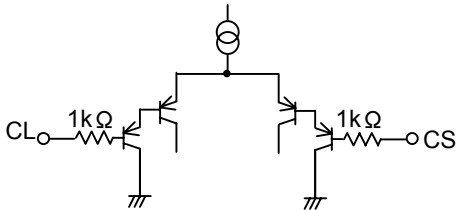
1) Hall input terminal



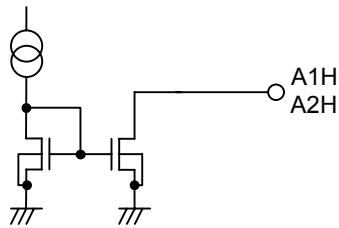
2) Charge and discharge pulse circuit capacitor
Resistor connecting terminal



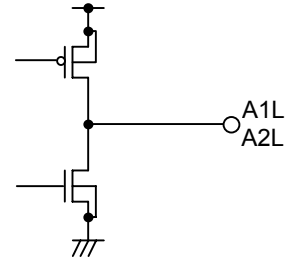
3) Current limiting input terminal
Output current detecting terminal



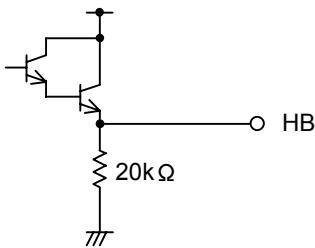
4) Output terminal on H side



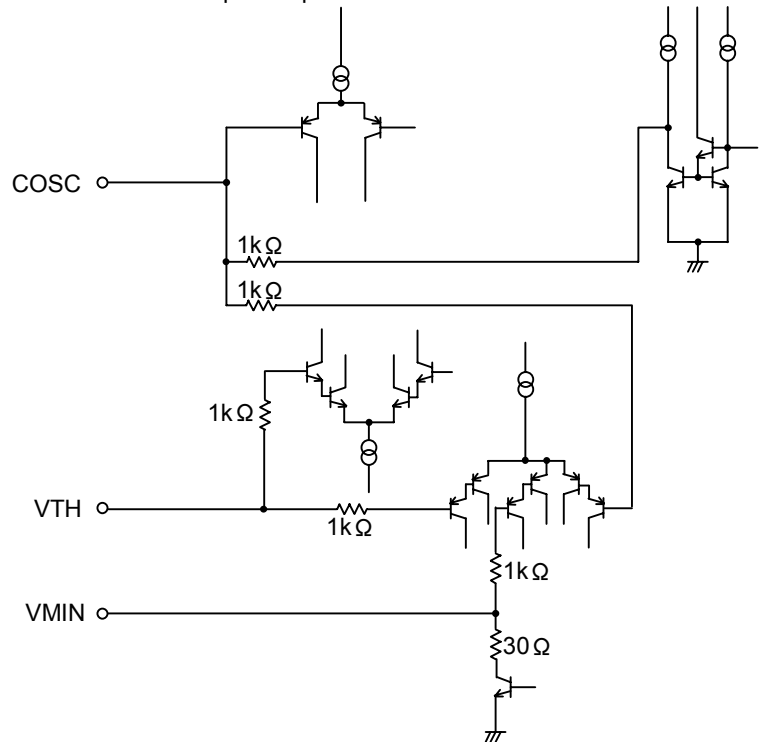
5) Output terminal on L side



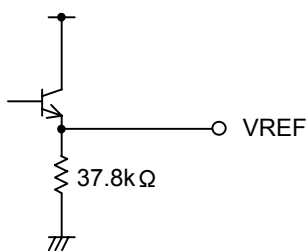
6) Hall bias terminal



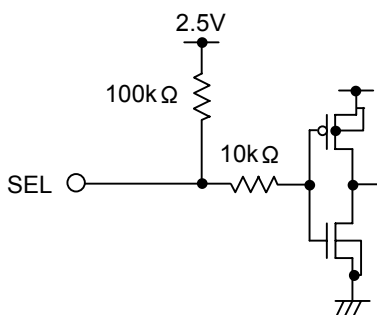
8) Oscillating capacitor connecting terminal
Variable speed input terminal (thermistor connecting terminal)
Minimum speed input terminal



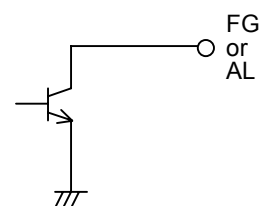
7) Reference voltage terminal



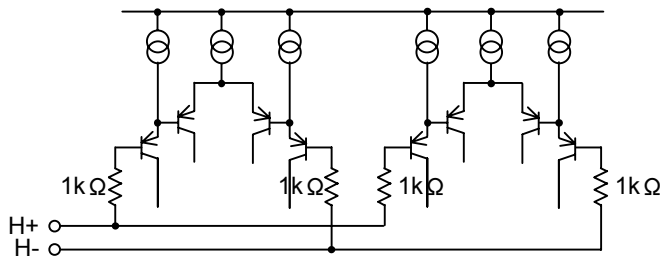
9) Lock detection ON:OFF ratio selecting terminal



10) FG output terminal or
AL output terminal

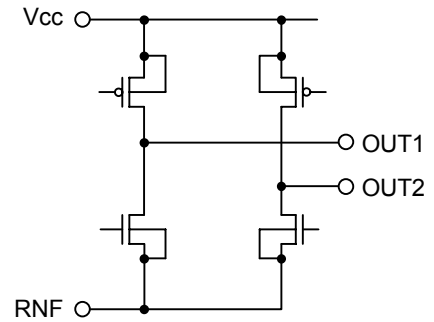


1) Hall input terminal

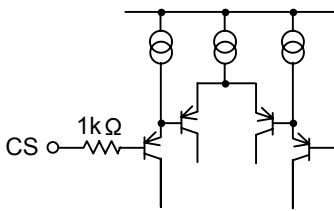


2) Motor output terminal

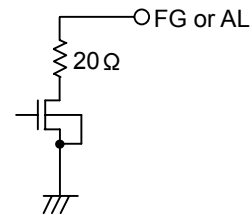
Output current detecting resistor connecting terminal



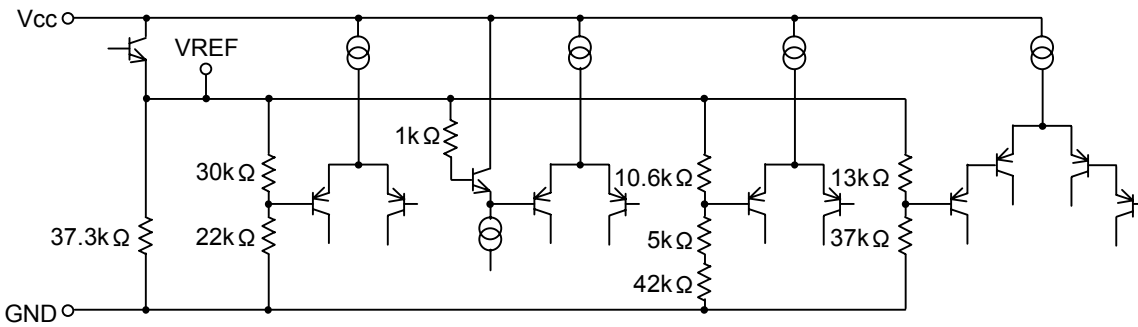
3) Output current detecting terminal



4) FG output terminal or AL output terminal



5) Reference voltage terminal



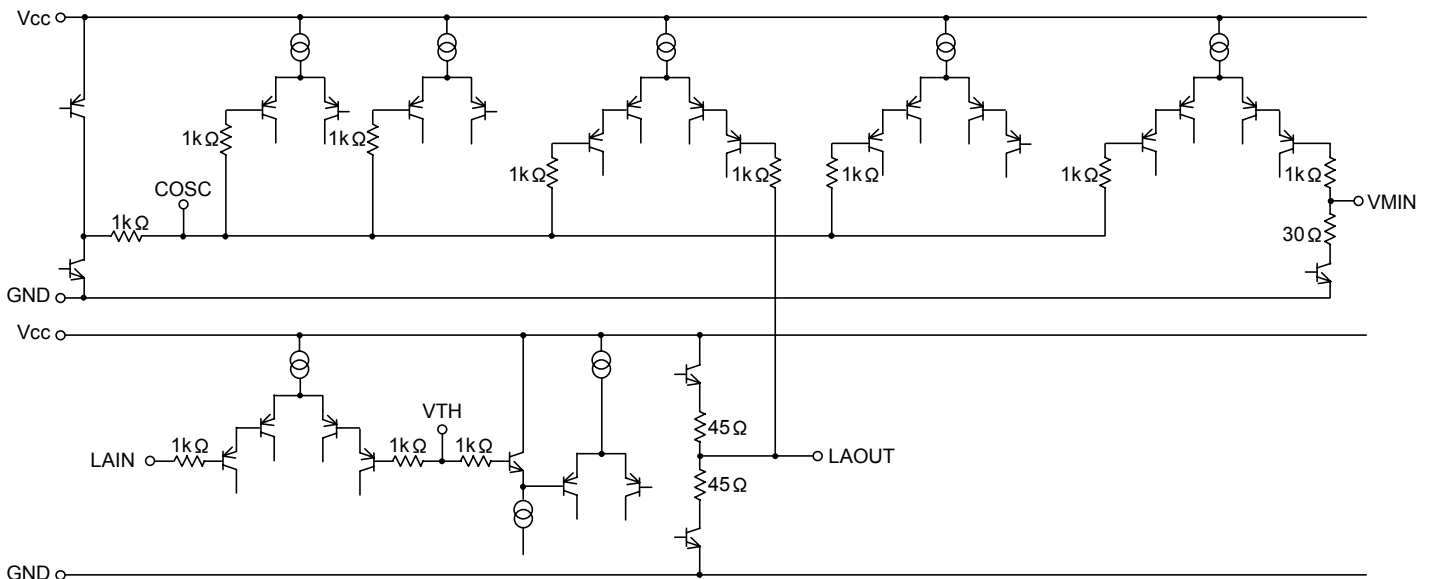
6) Oscillating capacitor connecting terminal

Variable amplifier input terminal (thermistor connecting terminal)

Level amplifier input terminal

Level amplifier output terminal

Minimum rotating speed setting terminal



● Safety measure

1) Reverse connection protection diode

Reverse connection of power results in IC destruction as shown in Fig.46. When reverse connection is possible, reverse connection protection diode must be added between power supply and Vcc.

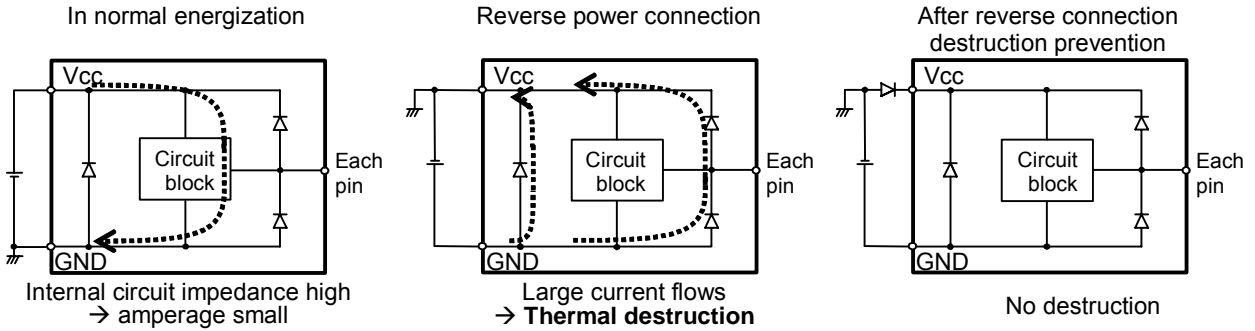


Fig.97 Flow of current when power is connected reversely

2) Measure against Vcc voltage rise by back electromotive force

Back electromotive force (Back EMF) generates regenerative current to power supply. However, when reverse connection protection diode is connected, Vcc voltage rises because the diode prevents current flow to power supply.

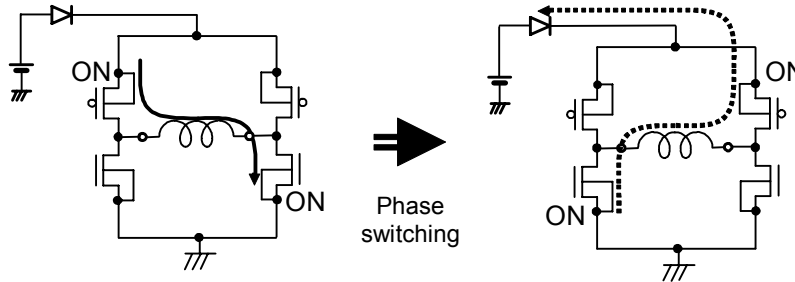


Fig.98 Vcc voltage rise by back electromotive force

When the absolute maximum rated voltage may be exceeded due to voltage rise by back electromotive force, place (A) Capacitor or (B) Zener diode between Vcc and GND. If necessary, add both (C).

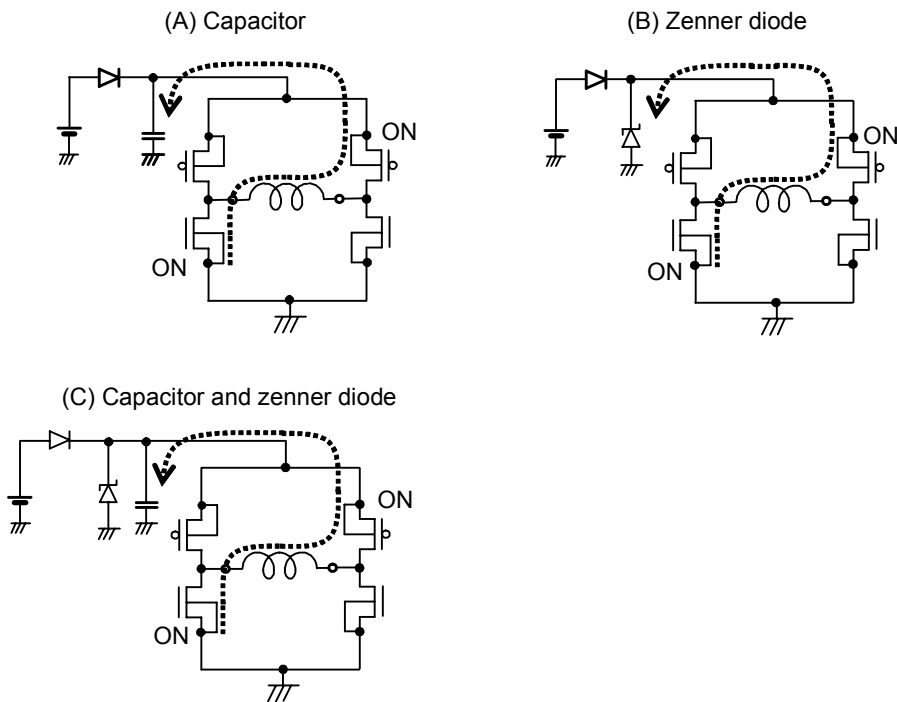


Fig.99 Measure against Vcc voltage rise

3) Problem of GND line PWM switching

Do not perform PWM switching of GND line because GND terminal potential cannot be kept to a minimum.

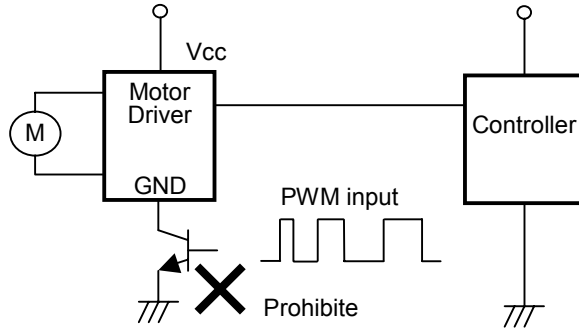


Fig.100 GND line PWM switching prohibited

4) FG and AL output

FG and AL output is an open collector and requires pull-up resistor.

The IC can be protected by adding resistor R1. An excess of absolute maximum rating, when FG or AL output terminal is directly connected to power supply, could damage the IC.

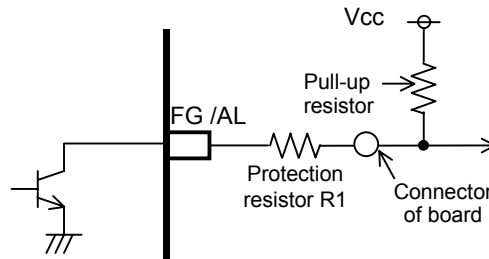


Fig.101 Protection of FG and AL terminal

● Calculation of power consumed by IC

Power consumed by this IC P_c is approximately calculated as follows:

$$P_c = P_{c1} + P_{c2} + P_{c3}$$

- P_{c1} : Power consumption by circuit current
 $P_{c1} = V_{cc} \times I_{cc}$
- P_{c2} : Power consumption at output stage
 $P_{c2} = V_{OL} \times I_o + V_{OH} \times I_o$
 V_{OL} is L voltage of output terminal 1 and 2.
 V_{OH} is H voltage of output terminal 1 and 2.
 I_o is the current flowing to output terminal 1 and 2.
- P_{c3} : Power consumption at FG and AL
 $P_{c3} = V_{FG} \times I_{FG} + V_{AL} \times I_{AL}$
 V_{FG} is L voltage of FG output.
 V_{AL} is L voltage of AL output.
 I_{FG} and I_{AL} are the current of FG and AL.

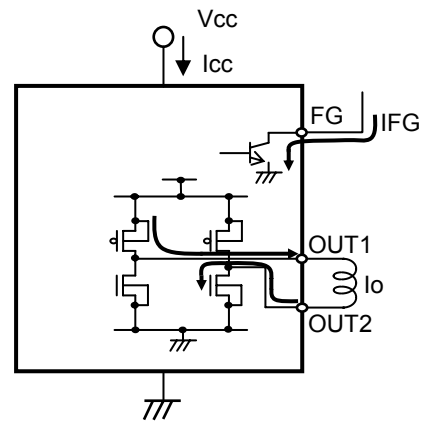


Fig.102 Calculation of power consumed by

Power consumption by IC greatly changes with use condition of IC such as power supply voltage and output current. Consider thermal design so that the maximum power dissipation on IC package is not exceeded.

● Thermal derating curve

Power dissipation (total loss) indicates the power that can be consumed by IC at Ta = 25°C (normal temperature). IC is heated when it consumes power, and the temperature of IC chip becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, etc, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip (maximum junction temperature) and thermal resistance of package (heat dissipation capability). The maximum junction temperature is in general equal to the maximum value in the storage temperature range.

Heat generated by consumed power of IC is radiated from the mold resin or lead frame of package. The parameter which indicates this heat dissipation capability (hardness of heat release) is called heat resistance, represented by the symbol θ_{ja} [°C/W]. The temperature of IC inside the package can be estimated by this heat resistance. Fig.37 shows the model of heat resistance of the package.

Heat resistance θ_{ja} , ambient temperature Ta, junction temperature Tj, and power consumption P can be calculated by the equation below:

$$\theta_{ja} = (T_j - T_a) / P \quad [^{\circ}\text{C}/\text{W}]$$

Thermal derating curve indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance θ_{ja} .

Thermal resistance θ_{ja} depends on chip size, power consumption, package ambient temperature, packaging condition, wind velocity, etc., even when the same package is used. Thermal derating curve indicates a reference value measured at a specified condition. Fig.38 shows a thermal derating curve (Value when mounting FR4 glass epoxy board 70 [mm] x 70 [mm] x 1.6 [mm] (copper foil area below 3 [%]))

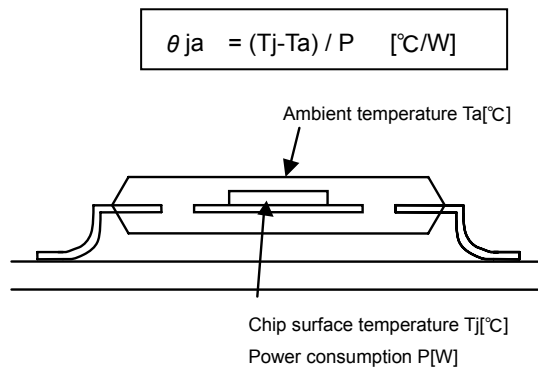
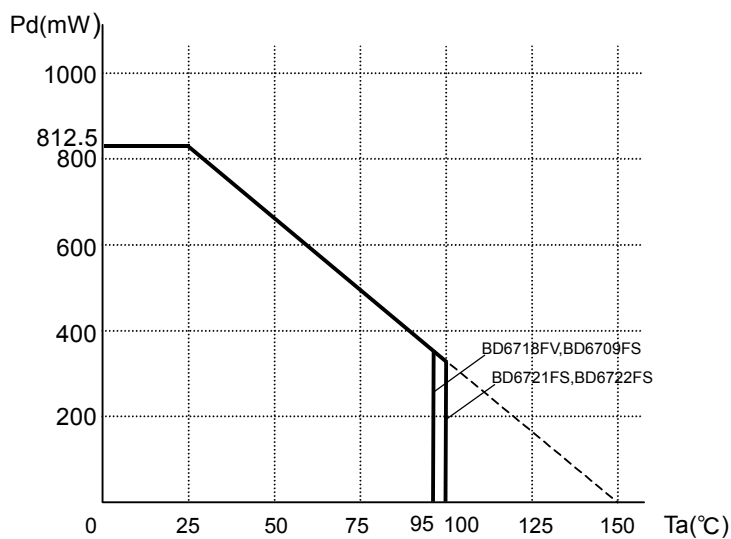


Fig.103 Thermal resistance



* Reduce by 6.5mW/°C over 25°C.
(On 70.0mm x 70.0mm x 1.6mm glass epoxy board)

Fig.104 Thermal derating curve

● Cautions on use

1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2) Connecting the power supply connector backward

Connecting of the power supply in reverse polarity can damage IC. Take precautions when connecting the power supply lines. An external direction diode can be added.

3) Power supply line

Back electromotive force causes regenerated current to power supply line, therefore take a measure such as placing a capacitor between power supply and GND for routing regenerated current. And fully ensure that the capacitor characteristics have no problem before determine a capacitor value. (when applying electrolytic capacitors, capacitance characteristic values are reduced at low temperatures)

4) GND potential

The potential of GND pin must be minimum potential in all operating conditions. Also ensure that all terminals except GND terminal do not fall below GND voltage including transient characteristics. However, it is possible that the motor output terminal may deflect below GND because of influence by back electromotive force of motor. Malfunction may possibly occur depending on use condition, environment, and property of individual motor. Please make fully confirmation that no problem is found on operation of IC.

5) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation(Pd) in actual operating conditions.

6) Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

7) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

8) ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

9) Thermal shut down circuit

The IC incorporates a built-in thermal shutdown circuit (TSD circuit). Operation temperature is 175°C(typ.) and has a hysteresis width of 25°C(typ.). When IC chip temperature rises and TSD circuit works, the output terminal becomes an open state. TSD circuit is designed only to shut the IC off to prevent thermal runaway. It is not designed to protect the IC or guarantee its operation. Do not continue to use the IC after operation this circuit or use the IC in an environment where the operation of this circuit is assumed.

10) Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.

11) GND wiring pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

12) Capacitor between output and GND

When a large capacitor is connected between output and GND, if Vcc is shorted with 0V or GND for some cause, it is possible that the current charged in the capacitor may flow into the output resulting in destruction. Keep the capacitor between output and GND below 100uF.

13) IC terminal input

When Vcc voltage is not applied to IC, do not apply voltage to each input terminal. When voltage above Vcc or below GND is applied to the input terminal, parasitic element is actuated due to the structure of IC. Operation of parasitic element causes mutual interference between circuits, resulting in malfunction as well as destruction in the last. Do not use in a manner where parasitic element is actuated.

14) In use

We are sure that the example of application circuit is preferable, but please check the character further more in application to a part which requires high precision. In using the unit with external circuit constant changed, consider the variation of externally equipped parts and our IC including not only static character but also transient character and allow sufficient margin in determining.

● Ordering part number

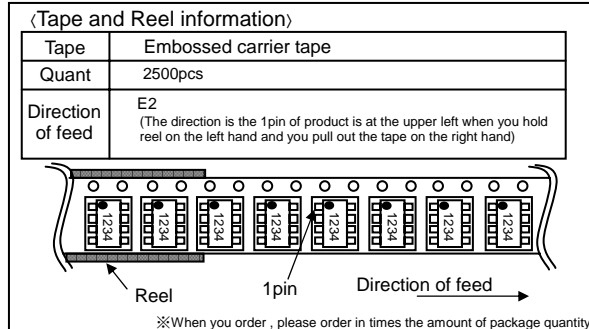
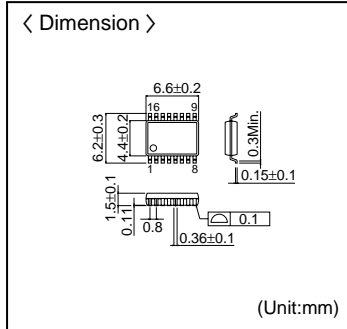
• Please order by ordering part number. • Please confirm the combination of each items. • Please write the letter close to left when column is blank.



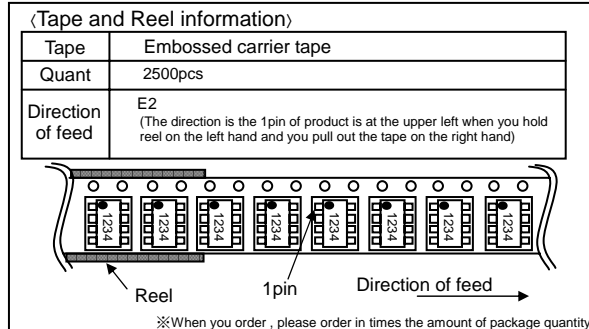
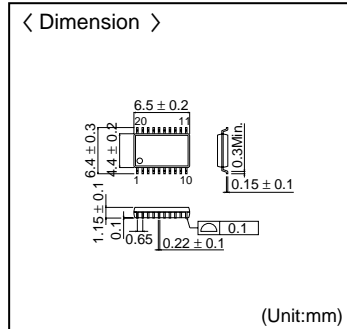
| | | |
|----------------------|---------------------|---|
| Part Number | Package Type | Package specification |
| • BD6709 • BD6718 | • FS : SSOP-A16 | E2 Emboss tape reel Pin 1 opposite draw-out side |
| • BD6721 • BD6722 | • FV : SSOP-B20 | |

● Physical dimension

SSOP-A16



SSOP-B20



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